

# BD135/137/139

# Medium Power Linear and Switching Applications

• Complement to BD136, BD138 and BD140 respectively



# **NPN Epitaxial Silicon Transistor**

# Absolute Maximum Ratings $T_C=25^{\circ}C$ unless otherwise noted

Symbol	Para	meter	Value	Units
$V_{CBO}$	Collector-Base Voltage	: BD135	45	V
		: BD137	60	V
		: BD139	80	V
V <sub>CEO</sub>	Collector-Emitter Voltage	: BD135	45	V
		: BD137	60	V
		: BD139	80	V
V <sub>EBO</sub>	Emitter-Base Voltage		5	V
I <sub>C</sub>	Collector Current (DC)		1.5	Α
I <sub>CP</sub>	Collector Current (Pulse)		3.0	Α
I <sub>B</sub>	Base Current		0.5	Α
P <sub>C</sub>	Collector Dissipation (T <sub>C</sub> =25°C	C)	12.5	W
P <sub>C</sub>	Collector Dissipation (T <sub>a</sub> =25°C	3)	1.25	W
T <sub>J</sub>	Junction Temperature		150	°C
T <sub>STG</sub>	Storage Temperature		- 55 ~ 150	°C

# Electrical Characteristics $T_C=25$ °C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
V <sub>CEO</sub> (sus)	Collector-Emitter Sustaining Voltage : BD135	$I_{C} = 30 \text{mA}, I_{B} = 0$	45			V
	: BD137 : BD139		60 80			V V
I <sub>CBO</sub>	Collector Cut-off Current	$V_{CB} = 30V, I_{E} = 0$			0.1	μΑ
I <sub>EBO</sub>	Emitter Cut-off Current	$V_{EB} = 5V, I_{C} = 0$			10	μΑ
h <sub>FE1</sub> h <sub>FE2</sub> h <sub>FE3</sub>	DC Current Gain : ALL DEVICE : ALL DEVICE : BD135 : BD137, BD139	$V_{CE} = 2V, I_{C} = 5mA$ $V_{CE} = 2V, I_{C} = 0.5A$ $V_{CE} = 2V, I_{C} = 150mA$	25 25 40 40		250 160	
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	$I_C = 500 \text{mA}, I_B = 50 \text{mA}$			0.5	V
V <sub>BE</sub> (on)	Base-Emitter ON Voltage	$V_{CE} = 2V, I_{C} = 0.5A$			1	V

# **h**<sub>FE</sub> Classification

Classification	6	10	16
h <sub>FE3</sub>	40 ~ 100	63 ~ 160	100 ~ 250

# **Typical Characteristics**

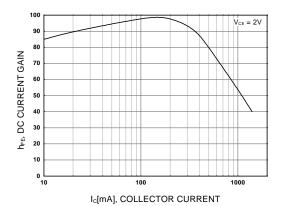


Figure 1. DC current Gain

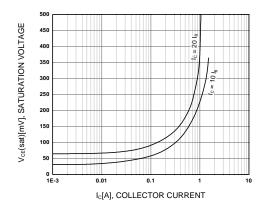


Figure 2. Collector-Emitter Saturation Voltage

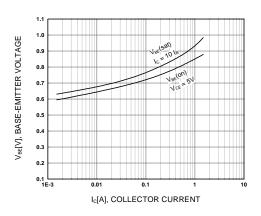


Figure 3. Base-Emitter Voltage

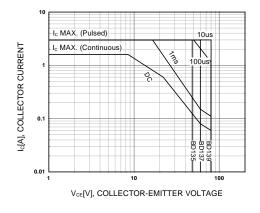


Figure 4. Safe Operating Area

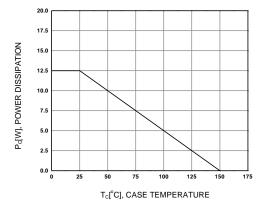
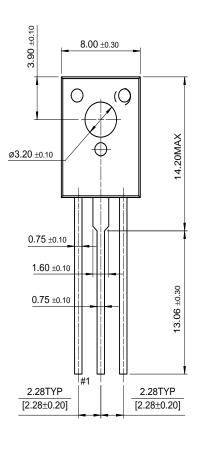
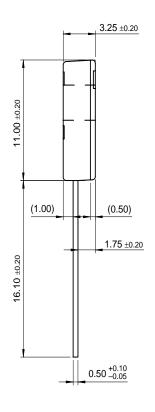


Figure 5. Power Derating

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Dimensions in Millimeters

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# HD44780U (LCD-II)

(Dot Matrix Liquid Crystal Display Controller/Driver)

# **HITACHI**

ADE-207-272(Z) '99.9 Rev. 0.0

## **Description**

The HD44780U dot-matrix liquid crystal display controller and driver LSI displays alphanumerics, Japanese kana characters, and symbols. It can be configured to drive a dot-matrix liquid crystal display under the control of a 4- or 8-bit microprocessor. Since all the functions such as display RAM, character generator, and liquid crystal driver, required for driving a dot-matrix liquid crystal display are internally provided on one chip, a minimal system can be interfaced with this controller/driver.

A single HD44780U can display up to one 8-character line or two 8-character lines.

The HD44780U has pin function compatibility with the HD44780S which allows the user to easily replace an LCD-II with an HD44780U. The HD44780U character generator ROM is extended to generate 208 5  $\times$  8 dot character fonts and 32 5  $\times$  10 dot character fonts for a total of 240 different character fonts.

The low power supply (2.7V to 5.5V) of the HD44780U is suitable for any portable battery-driven product requiring low power dissipation.

#### **Features**

- $5 \times 8$  and  $5 \times 10$  dot matrix possible
- Low power operation support:
  - 2.7 to 5.5V
- Wide range of liquid crystal display driver power
  - 3.0 to 11V
- Liquid crystal drive waveform
  - A (One line frequency AC waveform)
- Correspond to high speed MPU bus interface
  - -2 MHz (when  $V_{CC} = 5V$ )
- 4-bit or 8-bit MPU interface enabled
- 80 × 8-bit display RAM (80 characters max.)
- 9,920-bit character generator ROM for a total of 240 character fonts
  - 208 character fonts ( $5 \times 8 \text{ dot}$ )
  - 32 character fonts ( $5 \times 10 \text{ dot}$ )

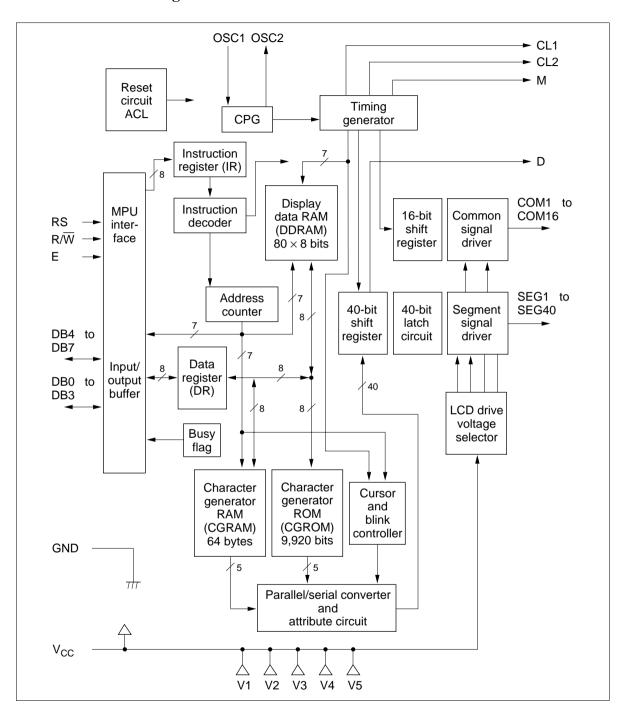
- 64 × 8-bit character generator RAM
  - -8 character fonts (5  $\times$  8 dot)
  - 4 character fonts  $(5 \times 10 \text{ dot})$
- 16-common × 40-segment liquid crystal display driver
- Programmable duty cycles
  - 1/8 for one line of  $5 \times 8$  dots with cursor
  - 1/11 for one line of  $5 \times 10$  dots with cursor
  - 1/16 for two lines of  $5 \times 8$  dots with cursor
- Wide range of instruction functions:
  - Display clear, cursor home, display on/off, cursor on/off, display character blink, cursor shift, display shift
- Pin function compatibility with HD44780S
- Automatic reset circuit that initializes the controller/driver after power on
- Internal oscillator with external resistors
- Low power consumption

## **Ordering Information**

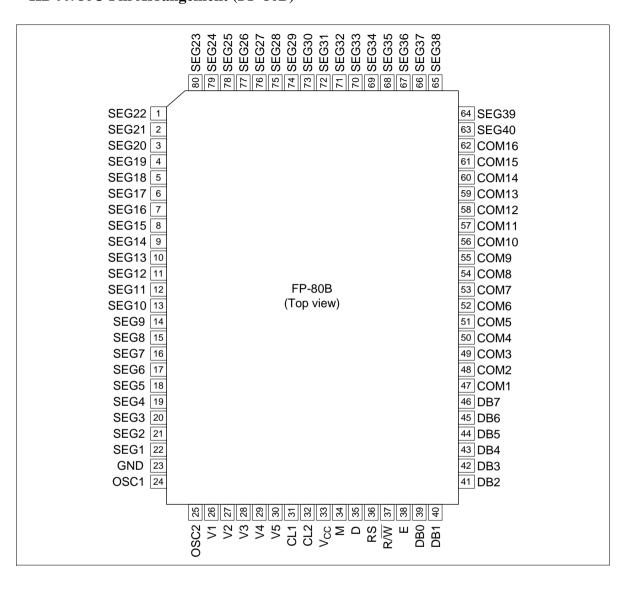
Type No.	Package	CGROM
HD44780UA00FS	FP-80B	Japanese standard font
HCD44780UA00	Chip	
HD44780UA00TF	TFP-80F	
HD44780UA02FS	FP-80B	European standard font
HCD44780UA02	Chip	
HD44780UA02TF	TFP-80F	
HD44780UBxxFS	FP-80B	Custom font
HCD44780UBxx	Chip	
HD44780UBxxTF	TFP-80F	

Note: xx: ROM code No.

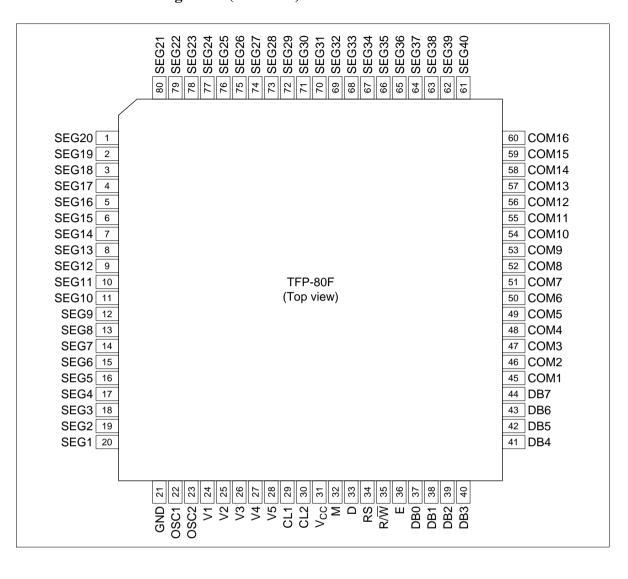
## **HD44780U Block Diagram**



## HD44780U Pin Arrangement (FP-80B)



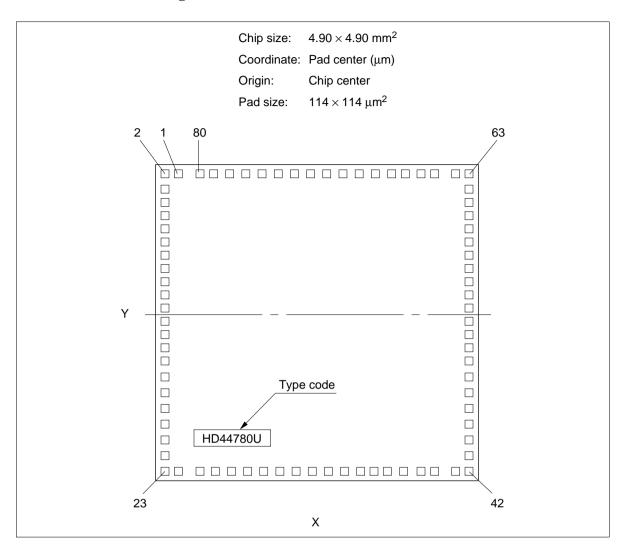
## **HD44780U Pin Arrangement (TFP-80F)**



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## **HD44780U Pad Arrangement**



# **HCD44780U Pad Location Coordinates**

		Cod	ordinate			Co	ordinate
Pad No.	Function	X (um)	Y (um)	Pad No.	Function	X (um)	Y (um)
1	SEG22	-2100	2313	41	DB2	2070	-2290
2	SEG21	-2280	2313	42	DB3	2260	-2290
3	SEG20	-2313	2089	43	DB4	2290	-2099
4	SEG19	-2313	1833	44	DB5	2290	-1883
5	SEG18	-2313	1617	45	DB6	2290	-1667
6	SEG17	-2313	1401	46	DB7	2290	-1452
7	SEG16	-2313	1186	47	COM1	2313	-1186
8	SEG15	-2313	970	48	COM2	2313	-970
9	SEG14	-2313	755	49	СОМЗ	2313	-755
10	SEG13	-2313	539	50	COM4	2313	-539
11	SEG12	-2313	323	51	COM5	2313	-323
12	SEG11	-2313	108	52	COM6	2313	-108
13	SEG10	-2313	-108	53	COM7	2313	108
14	SEG9	-2313	-323	54	COM8	2313	323
15	SEG8	-2313	-539	55	COM9	2313	539
16	SEG7	-2313	-755	56	COM10	2313	755
17	SEG6	-2313	-970	57	COM11	2313	970
18	SEG5	-2313	-1186	58	COM12	2313	1186
19	SEG4	-2313	-1401	59	COM13	2313	1401
20	SEG3	-2313	-1617	60	COM14	2313	1617
21	SEG2	-2313	-1833	61	COM15	2313	1833
22	SEG1	-2313	-2073	62	COM16	2313	2095
23	GND	-2280	-2290	63	SEG40	2296	2313
24	OSC1	-2080	-2290	64	SEG39	2100	2313
25	OSC2	-1749	-2290	65	SEG38	1617	2313
26	V1	-1550	-2290	66	SEG37	1401	2313
27	V2	-1268	-2290	67	SEG36	1186	2313
28	V3	-941	-2290	68	SEG35	970	2313
29	V4	-623	-2290	69	SEG34	755	2313
30	V5	-304	-2290	70	SEG33	539	2313
31	CL1	-48	-2290	71	SEG32	323	2313
32	CL2	142	-2290	72	SEG31	108	2313
33	V <sub>cc</sub>	309	-2290	73	SEG30	-108	2313
34	M	475	-2290	74	SEG29	-323	2313
35	D	665	-2290	75	SEG28	-539	2313
36	RS	832	-2290	76	SEG27	-755	2313
37	R/W	1022	-2290	77	SEG26	-970	2313
38	E	1204	-2290	78	SEG25	-1186	2313
39	DB0	1454	-2290	79	SEG24	-1401	2313
40	DB1	1684	-2290	80	SEG23	-1617	2313

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# **Pin Functions**

Signal	No. of Lines	I/O	Device Interfaced with	Function
RS	1	I	MPU	Selects registers. 0: Instruction register (for write) Busy flag: address counter (for read) 1: Data register (for write and read)
R/W	1	I	MPU	Selects read or write. 0: Write 1: Read
E	1	I	MPU	Starts data read/write.
DB4 to DB7	4	I/O	MPU	Four high order bidirectional tristate data bus pins. Used for data transfer and receive between the MPU and the HD44780U. DB7 can be used as a busy flag.
DB0 to DB3	4	I/O	MPU	Four low order bidirectional tristate data bus pins. Used for data transfer and receive between the MPU and the HD44780U. These pins are not used during 4-bit operation.
CL1	1	0	Extension driver	Clock to latch serial data D sent to the extension driver
CL2	1	0	Extension driver	Clock to shift serial data D
M	1	0	Extension driver	Switch signal for converting the liquid crystal drive waveform to AC
D	1	0	Extension driver	Character pattern data corresponding to each segment signal
COM1 to COM16	16	0	LCD	Common signals that are not used are changed to non-selection waveforms. COM9 to COM16 are non-selection waveforms at 1/8 duty factor and COM12 to COM16 are non-selection waveforms at 1/11 duty factor.
SEG1 to SEG40	40	0	LCD	Segment signals
V1 to V5	5	_	Power supply	Power supply for LCD drive V <sub>cc</sub> –V5 = 11 V (max)
V <sub>cc</sub> , GND	2	_	Power supply	V <sub>cc</sub> : 2.7V to 5.5V, GND: 0V
OSC1, OSC2	2	_	Oscillation resistor clock	When crystal oscillation is performed, a resistor must be connected externally. When the pin input is an external clock, it must be input to OSC1.

### **Function Description**

#### Registers

The HD44780U has two 8-bit registers, an instruction register (IR) and a data register (DR).

The IR stores instruction codes, such as display clear and cursor shift, and address information for display data RAM (DDRAM) and character generator RAM (CGRAM). The IR can only be written from the MPU.

The DR temporarily stores data to be written into DDRAM or CGRAM and temporarily stores data to be read from DDRAM or CGRAM. Data written into the DR from the MPU is automatically written into DDRAM or CGRAM by an internal operation. The DR is also used for data storage when reading data from DDRAM or CGRAM. When address information is written into the IR, data is read and then stored into the DR from DDRAM or CGRAM by an internal operation. Data transfer between the MPU is then completed when the MPU reads the DR. After the read, data in DDRAM or CGRAM at the next address is sent to the DR for the next read from the MPU. By the register selector (RS) signal, these two registers can be selected (Table 1).

#### Busy Flag (BF)

When the busy flag is 1, the HD44780U is in the internal operation mode, and the next instruction will not be accepted. When RS = 0 and  $R/\overline{W} = 1$  (Table 1), the busy flag is output to DB7. The next instruction must be written after ensuring that the busy flag is 0.

#### Address Counter (AC)

The address counter (AC) assigns addresses to both DDRAM and CGRAM. When an address of an instruction is written into the IR, the address information is sent from the IR to the AC. Selection of either DDRAM or CGRAM is also determined concurrently by the instruction.

After writing into (reading from) DDRAM or CGRAM, the AC is automatically incremented by 1 (decremented by 1). The AC contents are then output to DB0 to DB6 when RS = 0 and  $R/\overline{W}$  = 1 (Table 1).

Table 1 Register Selection

RS	R/W	Operation
0	0	IR write as an internal operation (display clear, etc.)
0	1	Read busy flag (DB7) and address counter (DB0 to DB6)
1	0	DR write as an internal operation (DR to DDRAM or CGRAM)
1	1	DR read as an internal operation (DDRAM or CGRAM to DR)

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#### **Display Data RAM (DDRAM)**

Display data RAM (DDRAM) stores display data represented in 8-bit character codes. Its extended capacity is  $80 \times 8$  bits, or 80 characters. The area in display data RAM (DDRAM) that is not used for display can be used as general data RAM. See Figure 1 for the relationships between DDRAM addresses and positions on the liquid crystal display.

The DDRAM address (A<sub>DD</sub>) is set in the address counter (AC) as hexadecimal.

- 1-line display (N = 0) (Figure 2)
  - When there are fewer than 80 display characters, the display begins at the head position. For example, if using only the HD44780, 8 characters are displayed. See Figure 3.

When the display shift operation is performed, the DDRAM address shifts. See Figure 3.

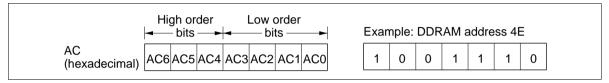


Figure 1 DDRAM Address

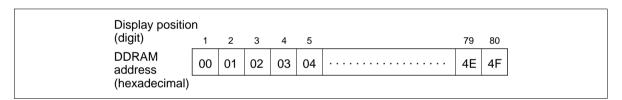


Figure 2 1-Line Display

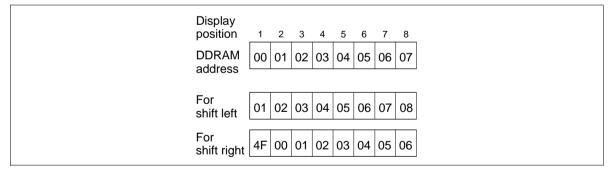


Figure 3 1-Line by 8-Character Display Example

- 2-line display (N = 1) (Figure 4)
  - Case 1: When the number of display characters is less than 40 × 2 lines, the two lines are displayed from the head. Note that the first line end address and the second line start address are not consecutive. For example, when just the HD44780 is used, 8 characters × 2 lines are displayed. See Figure 5.

When display shift operation is performed, the DDRAM address shifts. See Figure 5.

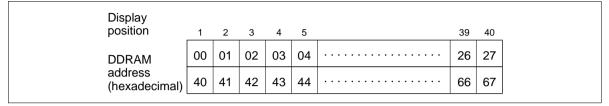


Figure 4 2-Line Display

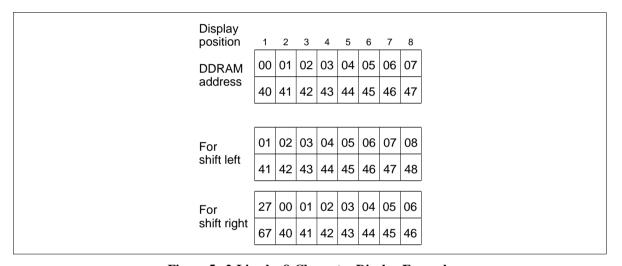


Figure 5 2-Line by 8-Character Display Example

— Case 2: For a 16-character × 2-line display, the HD44780 can be extended using one 40-output extension driver. See Figure 6.

When display shift operation is performed, the DDRAM address shifts. See Figure 6.

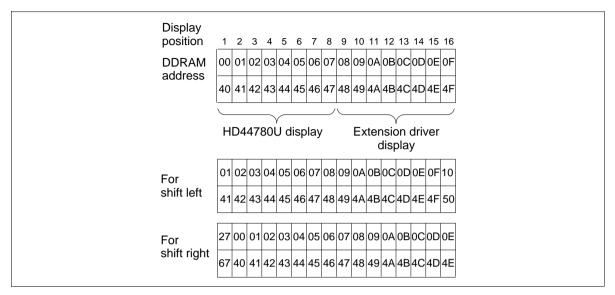


Figure 6 2-Line by 16-Character Display Example

#### **Character Generator ROM (CGROM)**

The character generator ROM generates  $5 \times 8$  dot or  $5 \times 10$  dot character patterns from 8-bit character codes (Table 4). It can generate  $208.5 \times 8$  dot character patterns and  $32.5 \times 10$  dot character patterns. User-defined character patterns are also available by mask-programmed ROM.

#### **Character Generator RAM (CGRAM)**

In the character generator RAM, the user can rewrite character patterns by program. For  $5 \times 8$  dots, eight character patterns can be written, and for  $5 \times 10$  dots, four character patterns can be written.

Write into DDRAM the character codes at the addresses shown as the left column of Table 4 to show the character patterns stored in CGRAM.

See Table 5 for the relationship between CGRAM addresses and data and display patterns.

Areas that are not used for display can be used as general data RAM.

#### **Modifying Character Patterns**

Character pattern development procedure

The following operations correspond to the numbers listed in Figure 7:

- 1. Determine the correspondence between character codes and character patterns.
- 2. Create a listing indicating the correspondence between EPROM addresses and data.
- 3. Program the character patterns into the EPROM.
- 4. Send the EPROM to Hitachi.
- 5. Computer processing on the EPROM is performed at Hitachi to create a character pattern listing, which is sent to the user.
- 6. If there are no problems within the character pattern listing, a trial LSI is created at Hitachi and samples are sent to the user for evaluation. When it is confirmed by the user that the character patterns are correctly written, mass production of the LSI proceeds at Hitachi.

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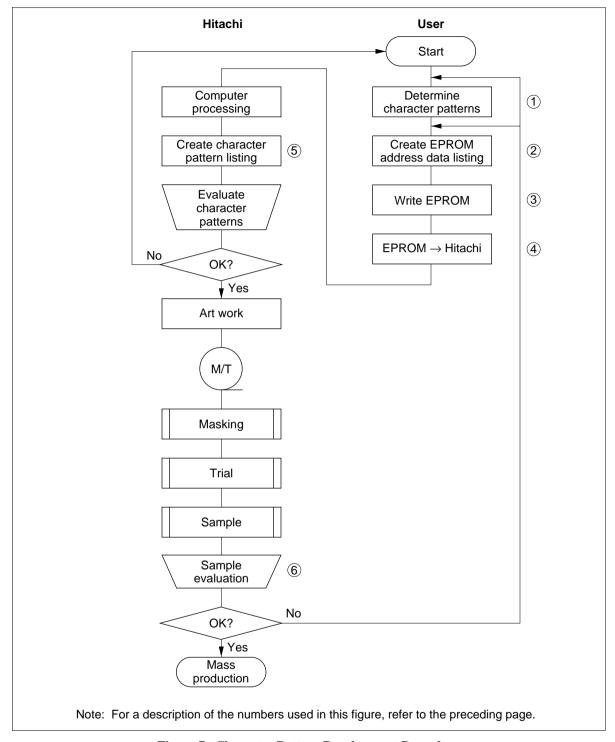


Figure 7 Character Pattern Development Procedure

#### • Programming character patterns

This section explains the correspondence between addresses and data used to program character patterns in EPROM. The HD44780U character generator ROM can generate  $208.5 \times 8$  dot character patterns and  $32.5 \times 10$  dot character patterns for a total of 240 different character patterns.

#### - Character patterns

EPROM address data and character pattern data correspond with each other to form a  $5 \times 8$  or  $5 \times 10$  dot character pattern (Tables 2 and 3).

Table 2 Example of Correspondence between EPROM Address Data and Character Pattern  $(5 \times 8 \text{ Dots})$ 

				EPI	RON	/I Ac	ddre	ss						Data	a		
A 1	1A1	0 A 9	Α8	Α7	Α6	A5	Α4	А3	A2	Α1	Α0	04	О3	02		LSB O0	
								0	0	0	0	1	0	0	0	0	
								0	0	0	1	1	0	0	0	0	
								0	0	1	0	1	0	1	1	0	
								0	0	1	1	1	1	0	0	1	
								0	1	0	0	1	0	0	0	1	
								0	1	0	1	1	0	0	0	1	
								0	1	1	0	1	1	1	1	0	
0	1	1	0	0	0	1	0	0	1	1	1	0	0	0	0	0	Cursor position
								1	0	0	0	0	0	0	0	0	
								1	0	0	1	0	0	0	0	0	
								1	0	1	0	0	0	0	0	0	
								1	0	1	1	0	0	0	0	0	
								1	1	0	0	0	0	0	0	0	
								1	1	0	1	0	0	0	0	0	
								1	1	1	0	0	0	0	0	0	
								1	1	1	1	0	0	0	0	0	
	(	Chara	acte	r co	de				Lir	ie							

position

Notes: 1. EPROM addresses A11 to A4 correspond to a character code.

- 2. EPROM addresses A3 to A0 specify a line position of the character pattern.
- 3. EPROM data O4 to O0 correspond to character pattern data.
- 4. EPROM data O5 to O7 must be specified as 0.
- 5. A lit display position (black) corresponds to a 1.
- 6. Line 9 and the following lines must be blanked with 0s for a  $5 \times 8$  dot character fonts.

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- Handling unused character patterns
- 1. EPROM data outside the character pattern area: Always input 0s.
- 2. EPROM data in CGRAM area: Always input 0s. (Input 0s to EPROM addresses 00H to FFH.)
- 3. EPROM data used when the user does not use any HD44780U character pattern: According to the user application, handled in one of the two ways listed as follows.
  - a. When unused character patterns are not programmed: If an unused character code is written into DDRAM, all its dots are lit. By not programing a character pattern, all of its bits become lit. (This is due to the EPROM being filled with 1s after it is erased.)
  - b. When unused character patterns are programmed as 0s: Nothing is displayed even if unused character codes are written into DDRAM. (This is equivalent to a space.)

Table 3 Example of Correspondence between EPROM Address Data and Character Pattern  $(5 \times 10 \text{ Dots})$ 

						EPF	RON	ΛA	ddı	es	s						Data	а		
A 1	1	A 1	0 A	9	Α8	Α7	Α6	6 A	5 A	4	А3	A2	Α1	Α0	04	О3	02		SB O0	
											0	0	0	0	0	0	0	0	0	
											0	0	0	1	0	0	0	0	0	
											0	0	1	0	0	1	1	0	1	
											0	0	1	1	1	0	0	1	1	
											0	1	0	0	1	0	0	0	1	
											0	1	0	1	1	0	0	0	1	
										-	0	1	1	0	0	1	1	1	1	
0	)	1	0		1	0	0	1	0	'   '	0	1	1	1	0	0	0	0	1	
											1	0	0	0	0	0	0	0	1	
											1	0	0	1	0	0	0	0	1	
											1	0	1	0	0	0	0	0	0	← Cursor position
											1	0	1	1	0	0	0	0	0	
											1	1	0	0	0	0	0	0	0	
											1	1	0	1	0	0	0	0	0	
										'	1	1	1	0	0	0	0	0	0	
											1	1	1	1	0	0	0	0	0	
		(	Cha	ra	cter	cod	de					Lir	ne sitio	n						

position

Notes: 1. EPROM addresses A11 to A3 correspond to a character code.

- 2. EPROM addresses A3 to A0 specify a line position of the character pattern.
- 3. EPROM data O4 to O0 correspond to character pattern data.
- 4. EPROM data O5 to O7 must be specified as 0.
- 5. A lit display position (black) corresponds to a 1.
- 6. Line 11 and the following lines must be blanked with 0s for a  $5 \times 10$  dot character fonts.

Table 4 Correspondence between Character Codes and Character Patterns (ROM Code: A00)

Upper 4 Lower Bits 4 Bits	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
xxxx0000	CG RAM (1)						*•	<b></b>					-:::			
xxxx0001	(2)															
xxxx0010	(3)							<b>!-"-</b>			:		•	.:: <sup>1</sup>		
xxxx0011	(4)					====	<b>:</b>								==-	***
xxxx0100	(5)			4				₩.			٠.		<b>!</b>			
xxxx0101	(6)							<b></b>			#				====	
xxxx0110	(7)							ı,ı								-
xxxx0111	(8)			:				ļļļ!					<b></b>			711
xxxx1000	(1)		<b>!</b>			×		×			-¶*				-,=	*
xxxx1001	(2)		<b>,</b>										, i		[	
xxxx1010	(3)		#:	==									: 1	<u>.</u>		
xxxx1011	(4)			;							<b>#</b>				** *:	<b>.</b>
xxxx1100	(5)			₹							-	<b></b> :			-	
xxxx1101	(6)						i i						•••	I	#	
xxxx1110	(7)		==	>			<b>!"</b> :							•••		
xxxx1111	(8)			•			====	<b>-</b>			• 1.1	<b></b> !	:			

Note: The user can specify any pattern for character-generator RAM.

 Table 4
 Correspondence between Character Codes and Character Patterns (ROM Code: A02)

Upper 4																
Lower Bits 4 Bits	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
xxxx0000	CG RAM (1)						**									
xxxx0001	(2)		i								-					
xxxx0010	(3)	##	11					<b>!-"-</b>								::
xxxx0011	(4)	##					===	-:::								::
xxxx0100	(5)			4				<b>.</b>		:	<b>:=:</b>					:::::
xxxx0101	(6)		#					11		::::				::::		
xxxx0110	(7)					Ņ		i.,:	.!!		1					====
xxxx0111	(8)	#	;			W		i,,i		-"	\$	==		×	:::-	
xxxx1000	(1)	-#-	ť.			X	<b>!</b> :	×	<u></u>	#		₩				.#-
xxxx1001	(2)		<u>;</u> ;			1	*	!				1.				
xxxx1010	(3)	-#-	#:	==	=											
xxxx1011	(4)	-		::	K			•			*	*				
xxxx1100	(5)	<	:	<.		٠.										
xxxx1101	(6)	<u>:</u>						<u>:</u>				<u> </u>		÷	-	
xxxx1110	(7)			>	<b>!</b> !	.**.	<b>!</b> -"!									
xxxx1111	(8)			•					-		#	<u>:</u> .			-	

# Table 5 Relationship between CGRAM Addresses, Character Codes (DDRAM) and Character Patterns (CGRAM Data)

For 5 × 8 dot character patterns

Character Codes (DDRAM data)	CGRAM Address	Character Patterns (CGRAM data)	
7 6 5 4 3 2 1 0	5 4 3 2 1 0	7 6 5 4 3 2 1 0	
High Low	High Low	High Low	
0 0 0 0 * 0 0 0	0 0 0 0 0 0 0 0 1 0 1 0 0 1 1 1 1 0 0 1	* * * * 1 1 1 1 1 0 1 0 0 0 1 1 0 0 0 1 1 1 1 1	Character pattern (1)  Cursor position
0 0 0 0 * 0 0 1	0 0 0 0 0 1 0 1 0 0 1 1 1 0 0 1 0 1 1 1 1	* * * 1 0 0 0 1 0 1 0 1 0 1 1 1 1 1 0 0 1 0 0 1 1 1 1	Character pattern (2)  Cursor position
	0 0 0 0 0 0 0 1	* * *	
0 0 0 0 * 1 1 1	1 1 1 1 0 0 1 0 1 1 1 0 1 1 1	* * *	

Notes: 1. Character code bits 0 to 2 correspond to CGRAM address bits 3 to 5 (3 bits: 8 types).

- CGRAM address bits 0 to 2 designate the character pattern line position. The 8th line is the
  cursor position and its display is formed by a logical OR with the cursor.
   Maintain the 8th line data, corresponding to the cursor display position, at 0 as the cursor display.
   If the 8th line data is 1, 1 bits will light up the 8th line regardless of the cursor presence.
- 3. Character pattern row positions correspond to CGRAM data bits 0 to 4 (bit 4 being at the left).
- 4. As shown Table 5, CGRAM character patterns are selected when character code bits 4 to 7 are all 0. However, since character code bit 3 has no effect, the R display example above can be selected by either character code 00H or 08H.
- 5. 1 for CGRAM data corresponds to display selection and 0 to non-selection.
- \* Indicates no effect.

# Table 5 Relationship between CGRAM Addresses, Character Codes (DDRAM) and Character Patterns (CGRAM Data) (cont)

For 5 × 10 dot character patterns

Character Codes (DDRAM data)	CGRAM Address	Character Patterns (CGRAM data)	
7 6 5 4 3 2 1 0	5 4 3 2 1 0	7 6 5 4 3 2 1 0	
High Low	High Low	High Low	
	0 0 0 0	* * * 0 0 0 0 0	
	0 0 0 1		
	0 0 1 0	1 0 1 1 0	
	0 0 1 1	1 1 0 0 1	
	0 1 0 0	1 0 0 0 1	Character
0 0 0 0 * 0 0 *	0 0 0 1 0 1	1 0 0 0 1	pattern
	0 1 1 0	1 1 1 0	
	0 1 1 1	1 0 0 0 0	
	1 0 0 0	1 0 0 0 0	
	1 0 0 1	10000	J
	1 0 1 0	* * * 0 0 0 0 0	} Cursor position
	1 0 1 1	* * * * * * * *	
	1 1 0 0	1	
	1 1 0 1		
	1 1 1 0	🗡   🗡	
	1 1 1 1	* * *   * * * * *	
	0 0 0 0	* * * *	
	0 0 0 1	<b>†</b>	
0 0 0 0 * 1 1 *	1 1 1 0 0 1	▼	
	1 0 1 0	* * *	
	1 0 1 1	* * *   * * * * *	
	1 1 0 0	†   †	
	1 1 0 1		
	1 1 1 0	🔻	
	1 1 1 1	* * * * * * * *	

Notes: 1. Character code bits 1 and 2 correspond to CGRAM address bits 4 and 5 (2 bits: 4 types).

2. CGRAM address bits 0 to 3 designate the character pattern line position. The 11th line is the cursor position and its display is formed by a logical OR with the cursor.

Maintain the 11th line data corresponding to the cursor display position at 0 as the cursor display position.

Maintain the 11th line data corresponding to the cursor display position at 0 as the cursor display. If the 11th line data is "1", "1" bits will light up the 11th line regardless of the cursor presence. Since lines 12 to 16 are not used for display, they can be used for general data RAM.

- 3. Character pattern row positions are the same as  $5 \times 8$  dot character pattern positions.
- 4. CGRAM character patterns are selected when character code bits 4 to 7 are all 0. However, since character code bits 0 and 3 have no effect, the P display example above can be selected by character codes 00H, 01H, 08H, and 09H.
- 5. 1 for CGRAM data corresponds to display selection and 0 to non-selection.
- \* Indicates no effect.

#### **Timing Generation Circuit**

The timing generation circuit generates timing signals for the operation of internal circuits such as DDRAM, CGROM and CGRAM. RAM read timing for display and internal operation timing by MPU access are generated separately to avoid interfering with each other. Therefore, when writing data to DDRAM, for example, there will be no undesirable interferences, such as flickering, in areas other than the display area.

#### **Liquid Crystal Display Driver Circuit**

The liquid crystal display driver circuit consists of 16 common signal drivers and 40 segment signal drivers. When the character font and number of lines are selected by a program, the required common signal drivers automatically output drive waveforms, while the other common signal drivers continue to output non-selection waveforms.

Sending serial data always starts at the display data character pattern corresponding to the last address of the display data RAM (DDRAM).

Since serial data is latched when the display data character pattern corresponding to the starting address enters the internal shift register, the HD44780U drives from the head display.

#### **Cursor/Blink Control Circuit**

The cursor/blink control circuit generates the cursor or character blinking. The cursor or the blinking will appear with the digit located at the display data RAM (DDRAM) address set in the address counter (AC).

For example (Figure 8), when the address counter is 08H, the cursor position is displayed at DDRAM address 08H.

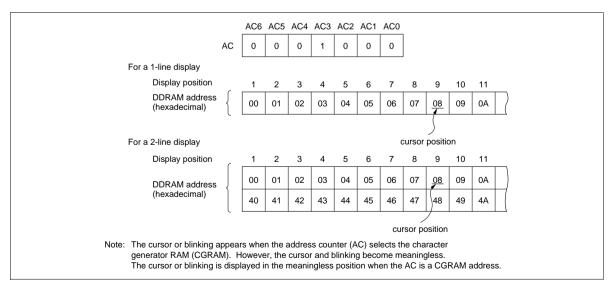


Figure 8 Cursor/Blink Display Example

### Interfacing to the MPU

The HD44780U can send data in either two 4-bit operations or one 8-bit operation, thus allowing interfacing with 4- or 8-bit MPUs.

- For 4-bit interface data, only four bus lines (DB4 to DB7) are used for transfer. Bus lines DB0 to DB3 are disabled. The data transfer between the HD44780U and the MPU is completed after the 4-bit data has been transferred twice. As for the order of data transfer, the four high order bits (for 8-bit operation, DB4 to DB7) are transferred before the four low order bits (for 8-bit operation, DB0 to DB3). The busy flag must be checked (one instruction) after the 4-bit data has been transferred twice. Two more 4-bit operations then transfer the busy flag and address counter data.
- For 8-bit interface data, all eight bus lines (DB0 to DB7) are used.

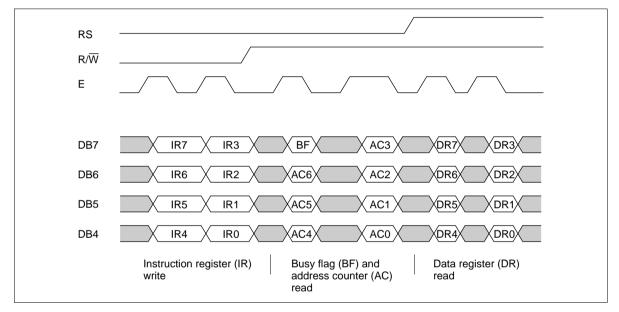


Figure 9 4-Bit Transfer Example

#### **Reset Function**

#### **Initializing by Internal Reset Circuit**

An internal reset circuit automatically initializes the HD44780U when the power is turned on. The following instructions are executed during the initialization. The busy flag (BF) is kept in the busy state until the initialization ends (BF = 1). The busy state lasts for 10 ms after  $V_{\rm CC}$  rises to 4.5 V.

- 1. Display clear
- 2. Function set:

DL = 1; 8-bit interface data

N = 0; 1-line display

F = 0;  $5 \times 8$  dot character font

- 3. Display on/off control:
  - D = 0; Display off
  - C = 0; Cursor off
  - B = 0; Blinking off
- 4. Entry mode set:
  - I/D = 1; Increment by 1
  - S = 0; No shift

Note: If the electrical characteristics conditions listed under the table Power Supply Conditions Using Internal Reset Circuit are not met, the internal reset circuit will not operate normally and will fail to initialize the HD44780U. For such a case, initial-ization must be performed by the MPU as explained in the section, Initializing by Instruction.

#### Instructions

#### Outline

Only the instruction register (IR) and the data register (DR) of the HD44780U can be controlled by the MPU. Before starting the internal operation of the HD44780U, control information is temporarily stored into these registers to allow interfacing with various MPUs, which operate at different speeds, or various peripheral control devices. The internal operation of the HD44780U is determined by signals sent from the MPU. These signals, which include register selection signal (RS), read/

write signal  $(R/\overline{W})$ , and the data bus (DB0 to DB7), make up the HD44780U instructions (Table 6). There are four categories of instructions that:

- Designate HD44780U functions, such as display format, data length, etc.
- Set internal RAM addresses
- Perform data transfer with internal RAM
- Perform miscellaneous functions

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Normally, instructions that perform data transfer with internal RAM are used the most. However, auto-incrementation by 1 (or auto-decrementation by 1) of internal HD44780U RAM addresses after each data write can lighten the program load of the MPU. Since the display shift instruction (Table 11) can perform concurrently with display data write, the user can minimize system development time with maximum programming efficiency.

When an instruction is being executed for internal operation, no instruction other than the busy flag/address read instruction can be executed.

Because the busy flag is set to 1 while an instruction is being executed, check it to make sure it is 0 before sending another instruction from the MPU.

Note: Be sure the HD44780U is not in the busy state (BF = 0) before sending an instruction from the MPU to the HD44780U. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself. Refer to Table 6 for the list of each instruction execution time.

Table 6 Instructions

					Co	ode						Execution Time (max) (when f <sub>cn</sub> or
Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description	f <sub>osc</sub> is 270 kHz)
Clear display	0	0	0	0	0	0	0	0	0	1	Clears entire display and sets DDRAM address 0 in address counter.	
Return home	0	0	0	0	0	0	0	0	1	_	Sets DDRAM address 0 in address counter. Also returns display from being shifted to original position. DDRAM contents remain unchanged.	1.52 ms
Entry mode set	0	0	0	0	0	0	0	1	I/D	S	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	37 μs
Display on/off control	0	0	0	0	0	0	1	D	С	В	Sets entire display (D) on/off, cursor on/off (C), and blinking of cursor position character (B).	37 μs
Cursor or display shift	0	0	0	0	0	1	S/C	R/L	_	_	Moves cursor and shifts display without changing DDRAM contents.	37 μs
Function set	0	0	0	0	1	DL	N	F	_	_	Sets interface data length (DL), number of display lines (N), and character font (F).	37 μs
Set CGRAM address	0	0	0	1	ACG	ACG	ACG	ACG	ACG	ACG	Sets CGRAM address. CGRAM data is sent and received after this setting.	37 μs
Set DDRAM address	0	0	1	ADD	Sets DDRAM address. DDRAM data is sent and received after this setting.	37 μs						
Read busy flag & address	0	1	BF	AC	Reads busy flag (BF) indicating internal operation is being performed and reads address counter contents.	0 μs						

Table 6 Instructions (cont)

	Code											Execution Time (max) (when f <sub>∞</sub> or	
Instruction	RS	R/W	DB7 DB6	DB5	DB4 DI	B3 DB2	DB1	DB0	Desc	ripti	on	f <sub>OSC</sub> is 270 kHz)	
Write data to CG or DDRAM	1	0	Write data						Write: CGR/		ta into DDRAM or	37 μs t <sub>ADD</sub> = 4 μs*	
Read data from CG or DDRAM	1	1	Read data						Read CGR		ta from DDRAM or	$37 \mu s$ $t_{ADD} = 4 \mu s^*$	
	I/D S S/C S/C R/L R/L	= 1: = 0: = 1: = 0: = 1: = 1:		ies displift ve right left = 0: 4 left s, F = 0	bits line ): 5×8				ACG:	AM: (corraddr Addr both	Display data RAM Character generator RAM CGRAM address DDRAM address responds to cursor ress) ress counter used for DD and CGRAM resses	Execution time changes when frequency changes Example: When $f_{cp}$ or $f_{OSC}$ is 250 kHz, $37 \ \mu s \times \frac{270}{250} = 40 \ \mu s$	

Note: — indicates no effect.

\* After execution of the CGRAM/DDRAM data write or read instruction, the RAM address counter is incremented or decremented by 1. The RAM address counter is updated after the busy flag turns off. In Figure 10, t<sub>ADD</sub> is the time elapsed after the busy flag turns off until the address counter is updated.

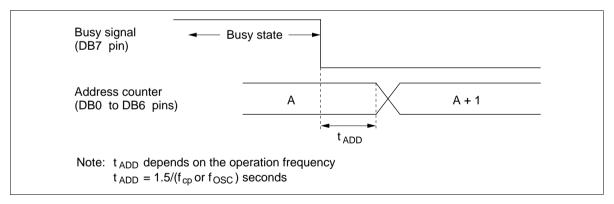


Figure 10 Address Counter Update

## **Instruction Description**

#### **Clear Display**

Clear display writes space code 20H (character pattern for character code 20H must be a blank pattern) into all DDRAM addresses. It then sets DDRAM address 0 into the address counter, and returns the display to its original status if it was shifted. In other words, the display disappears and the cursor or blinking goes to the left edge of the display (in the first line if 2 lines are displayed). It also sets I/D to 1 (increment mode) in entry mode. S of entry mode does not change.

#### **Return Home**

Return home sets DDRAM address 0 into the address counter, and returns the display to its original status if it was shifted. The DDRAM contents do not change.

The cursor or blinking go to the left edge of the display (in the first line if 2 lines are displayed).

#### **Entry Mode Set**

**I/D:** Increments (I/D = 1) or decrements (I/D = 0) the DDRAM address by 1 when a character code is written into or read from DDRAM.

The cursor or blinking moves to the right when incremented by 1 and to the left when decremented by 1. The same applies to writing and reading of CGRAM.

S: Shifts the entire display either to the right (I/D = 0) or to the left (I/D = 1) when S is 1. The display does not shift if S is 0.

If S is 1, it will seem as if the cursor does not move but the display does. The display does not shift when reading from DDRAM. Also, writing into or reading out from CGRAM does not shift the display.

#### **Display On/Off Control**

**D:** The display is on when D is 1 and off when D is 0. When off, the display data remains in DDRAM, but can be displayed instantly by setting D to 1.

C: The cursor is displayed when C is 1 and not displayed when C is 0. Even if the cursor disappears, the function of I/D or other specifications will not change during display data write. The cursor is displayed using 5 dots in the 8th line for  $5 \times 8$  dot character font selection and in the 11th line for the  $5 \times 10$  dot character font selection (Figure 13).

**B:** The character indicated by the cursor blinks when B is 1 (Figure 13). The blinking is displayed as switching between all blank dots and displayed characters at a speed of 409.6-ms intervals when  $f_{cp}$  or  $f_{OSC}$  is 250 kHz. The cursor and blinking can be set to display simultaneously. (The blinking frequency changes according to  $f_{OSC}$  or the reciprocal of  $f_{cp}$ . For example, when  $f_{cp}$  is 270 kHz,  $409.6 \times 250/270 = 379.2$  ms.)

### **Cursor or Display Shift**

Cursor or display shift shifts the cursor position or display to the right or left without writing or reading display data (Table 7). This function is used to correct or search the display. In a 2-line display, the cursor moves to the second line when it passes the 40th digit of the first line. Note that the first and second line displays will shift at the same time.

When the displayed data is shifted repeatedly each line moves only horizontally. The second line display does not shift into the first line position.

The address counter (AC) contents will not change if the only action performed is a display shift.

#### **Function Set**

**DL:** Sets the interface data length. Data is sent or received in 8-bit lengths (DB7 to DB0) when DL is 1, and in 4-bit lengths (DB7 to DB4) when DL is 0. When 4-bit length is selected, data must be sent or received twice.

N: Sets the number of display lines.

**F:** Sets the character font.

Note: Perform the function at the head of the program before executing any instructions (except for the read busy flag and address instruction). From this point, the function set instruction cannot be executed unless the interface data length is changed.

#### Set CGRAM Address

Set CGRAM address sets the CGRAM address binary AAAAAA into the address counter.

Data is then written to or read from the MPU for CGRAM.

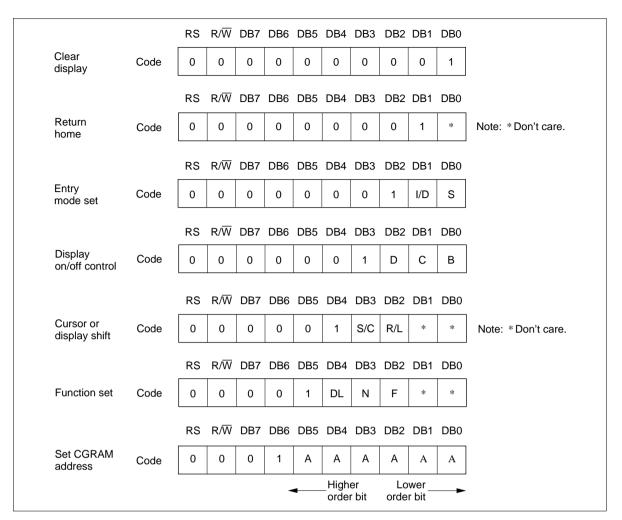


Figure 11 Instruction (1)

#### **Set DDRAM Address**

Set DDRAM address sets the DDRAM address binary AAAAAA into the address counter.

Data is then written to or read from the MPU for DDRAM.

However, when N is 0 (1-line display), AAAAAAA can be 00H to 4FH. When N is 1 (2-line display), AAAAAAA can be 00H to 27H for the first line, and 40H to 67H for the second line.

#### **Read Busy Flag and Address**

Read busy flag and address reads the busy flag (BF) indicating that the system is now internally operating on a previously received instruction. If BF is 1, the internal operation is in progress. The next instruction will not be accepted until BF is reset to 0. Check the BF status before the next write operation. At the same time, the value of the address counter in binary AAAAAA is read out. This address counter is used by both CG and DDRAM addresses, and its value is determined by the previous instruction. The address contents are the same as for instructions set CGRAM address and set DDRAM addresss.

Table 7 Shift Function

S/C	R/L	
0	0	Shifts the cursor position to the left. (AC is decremented by one.)
0	1	Shifts the cursor position to the right. (AC is incremented by one.)
1	0	Shifts the entire display to the left. The cursor follows the display shift.
1	1	Shifts the entire display to the right. The cursor follows the display shift.

Table 8 Function Set

N	F	No. of Display Lines	Character Font	Duty Factor	Remarks
0	0	1	$5 \times 8 \text{ dots}$	1/8	
0	1	1	$5 \times 10 \text{ dots}$	1/11	
1	*	2	5 × 8 dots	1/16	Cannot display two lines for 5 × 10 dot character font

Note: \* Indicates don't care.

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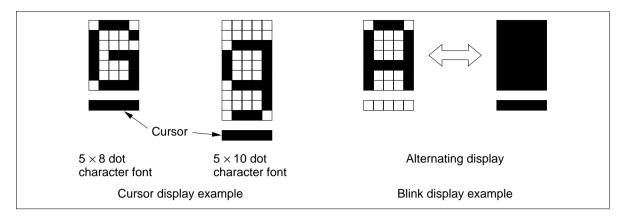


Figure 12 Cursor and Blinking

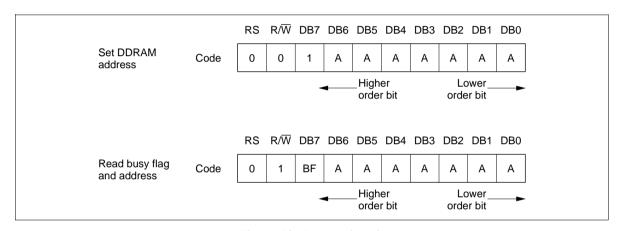


Figure 13 Instruction (2)

#### Write Data to CG or DDRAM

Write data to CG or DDRAM writes 8-bit binary data DDDDDDDD to CG or DDRAM.

To write into CG or DDRAM is determined by the previous specification of the CGRAM or DDRAM address setting. After a write, the address is automatically incremented or decremented by 1 according to the entry mode. The entry mode also determines the display shift.

#### Read Data from CG or DDRAM

Read data from CG or DDRAM reads 8-bit binary data DDDDDDDD from CG or DDRAM.

The previous designation determines whether CG or DDRAM is to be read. Before entering this read instruction, either CGRAM or DDRAM address set instruction must be executed. If not executed, the first read data will be invalid. When serially executing read instructions, the next address data is normally read from the second read. The address set instructions need not be executed just before this read instruction when shifting the cursor by the cursor shift instruction (when reading out DDRAM). The operation of the cursor shift instruction is the same as the set DDRAM address instruction.

After a read, the entry mode automatically increases or decreases the address by 1. However, display shift is not executed regardless of the entry mode.

Note: The address counter (AC) is automatically incremented or decremented by 1 after the write instructions to CGRAM or DDRAM are executed. The RAM data selected by the AC cannot be read out at this time even if read instructions are executed. Therefore, to correctly read data, execute either the address set instruction or cursor shift instruction (only with DDRAM), then just before reading the desired data, execute the read instruction from the second time the read instruction is sent.

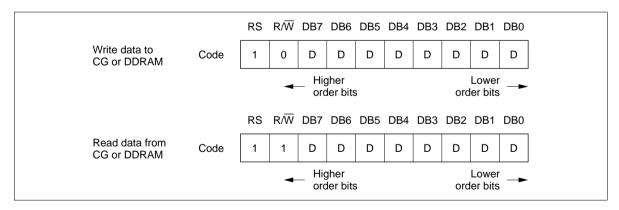


Figure 14 Instruction (3)

#### **Interfacing the HD44780U**

#### Interface to MPUs

• Interfacing to an 8-bit MPU

See Figure 16 for an example of using a I/O port (for a single-chip microcomputer) as an interface device.

In this example, P30 to P37 are connected to the data bus DB0 to DB7, and P75 to P77 are connected to E,  $R/\overline{W}$ , and RS, respectively.

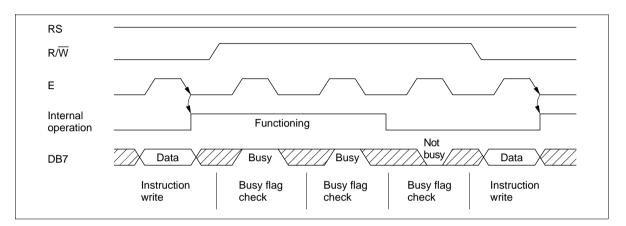


Figure 15 Example of Busy Flag Check Timing Sequence

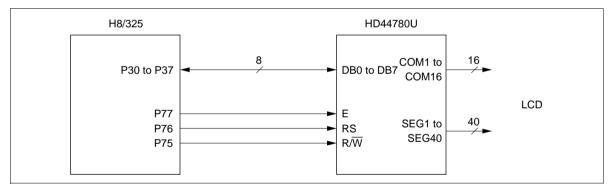


Figure 16 H8/325 Interface (Single-Chip Mode)

#### • Interfacing to a 4-bit MPU

The HD44780U can be connected to the I/O port of a 4-bit MPU. If the I/O port has enough bits, 8-bit data can be transferred. Otherwise, one data transfer must be made in two operations for 4-bit data. In this case, the timing sequence becomes somewhat complex. (See Figure 17.)

See Figure 18 for an interface example to the HMCS4019R.

Note that two cycles are needed for the busy flag check as well as for the data transfer. The 4-bit operation is selected by the program.

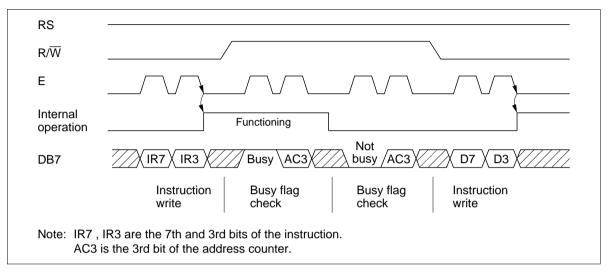


Figure 17 Example of 4-Bit Data Transfer Timing Sequence

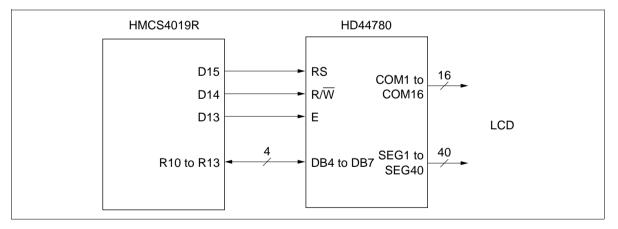


Figure 18 Example of Interface to HMCS4019R

#### **Interface to Liquid Crystal Display**

**Character Font and Number of Lines:** The HD44780U can perform two types of displays,  $5 \times 8$  dot and  $5 \times 10$  dot character fonts, each with a cursor.

Up to two lines are displayed for  $5 \times 8$  dots and one line for  $5 \times 10$  dots. Therefore, a total of three types of common signals are available (Table 9).

The number of lines and font types can be selected by the program. (See Table 6, Instructions.)

Connection to HD44780 and Liquid Crystal Display: See Figure 19 for the connection examples.

**Table 9** Common Signals

Number of Lines	Character Font	Number of Common Signals	<b>Duty Factor</b>
1	5 × 8 dots + cursor	8	1/8
1	5 × 10 dots + cursor	11	1/11
2	5 × 8 dots + cursor	16	1/16

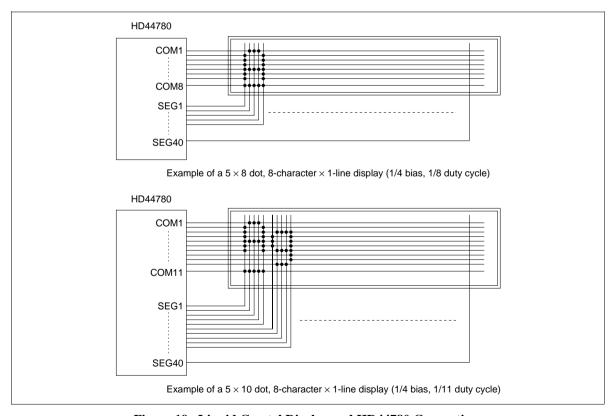


Figure 19 Liquid Crystal Display and HD44780 Connections

Since five segment signal lines can display one digit, one HD44780U can display up to 8 digits for a 1-line display and 16 digits for a 2-line display.

The examples in Figure 19 have unused common signal pins, which always output non-selection waveforms. When the liquid crystal display panel has unused extra scanning lines, connect the extra scanning lines to these common signal pins to avoid any undesirable effects due to crosstalk during the floating state.

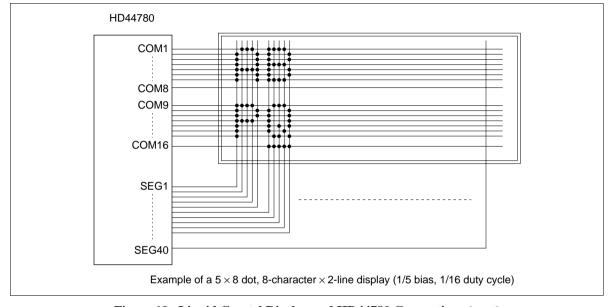


Figure 19 Liquid Crystal Display and HD44780 Connections (cont)

Connection of Changed Matrix Layout: In the preceding examples, the number of lines correspond to the scanning lines. However, the following display examples (Figure 20) are made possible by altering the matrix layout of the liquid crystal display panel. In either case, the only change is the layout. The display characteristics and the number of liquid crystal display characters depend on the number of common signals or on duty factor. Note that the display data RAM (DDRAM) addresses for 4 characters × 2 lines and for 16 characters × 1 line are the same as in Figure 19.

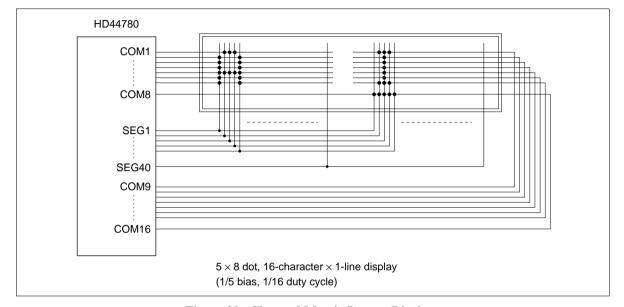


Figure 20 Changed Matrix Layout Displays

### Power Supply for Liquid Crystal Display Drive

Various voltage levels must be applied to pins V1 to V5 of the HD44780U to obtain the liquid crystal display drive waveforms. The voltages must be changed according to the duty factor (Table 10).

VLCD is the peak value for the liquid crystal display drive waveforms, and resistance dividing provides voltages V1 to V5 (Figure 21).

Table 10 Duty Factor and Power Supply for Liquid Crystal Display Drive

	Duty Factor								
	1/8, 1/11	1/16							
		Bias							
Power Supply	1/4	1/5							
V1	V <sub>cc</sub> -1/4 VLCD	V <sub>cc</sub> -1/5 VLCD							
V2	V <sub>cc</sub> -1/2 VLCD	V <sub>cc</sub> -2/5 VLCD							
V3	V <sub>cc</sub> -1/2 VLCD	V <sub>cc</sub> -3/5 VLCD							
V4	V <sub>cc</sub> -3/4 VLCD	V <sub>cc</sub> -4/5 VLCD							
V5	V <sub>cc</sub> -VLCD	V <sub>cc</sub> -VLCD							

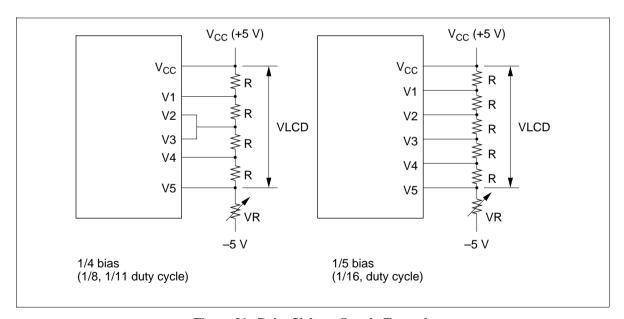


Figure 21 Drive Voltage Supply Example

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# Relationship between Oscillation Frequency and Liquid Crystal Display Frame Frequency

The liquid crystal display frame frequencies of Figure 22 apply only when the oscillation frequency is 270 kHz (one clock pulse of  $3.7 \,\mu s$ ).

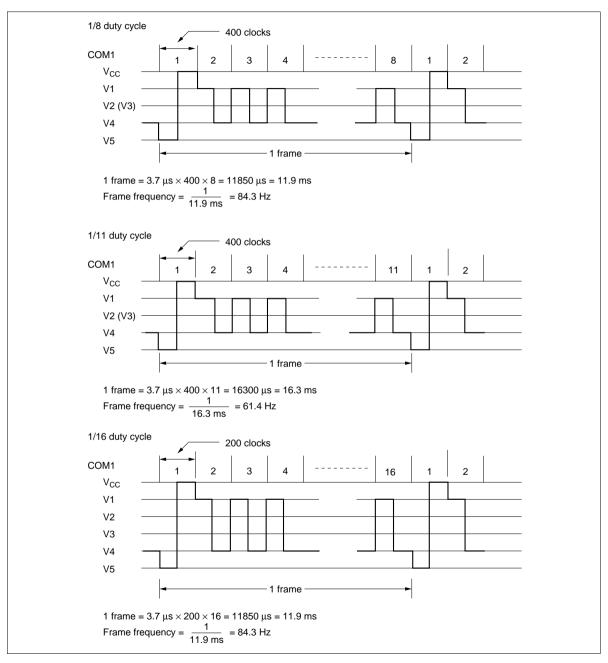


Figure 22 Frame Frequency

#### **Instruction and Display Correspondence**

- 8-bit operation, 8-digit × 1-line display with internal reset
  - Refer to Table 11 for an example of an 8-digit  $\times$  1-line display in 8-bit operation. The HD44780U functions must be set by the function set instruction prior to the display. Since the display data RAM can store data for 80 characters, as explained before, the RAM can be used for displays such as for advertising when combined with the display shift operation.
  - Since the display shift operation changes only the display position with DDRAM contents unchanged, the first display data entered into DDRAM can be output when the return home operation is performed.
- 4-bit operation, 8-digit × 1-line display with internal reset
  - The program must set all functions prior to the 4-bit operation (Table 12). When the power is turned on, 8-bit operation is automatically selected and the first write is performed as an 8-bit operation. Since DB0 to DB3 are not connected, a rewrite is then required. However, since one operation is completed in two accesses for 4-bit operation, a rewrite is needed to set the functions (see Table 12). Thus, DB4 to DB7 of the function set instruction is written twice.
- 8-bit operation, 8-digit × 2-line display
  - For a 2-line display, the cursor automatically moves from the first to the second line after the 40th digit of the first line has been written. Thus, if there are only 8 characters in the first line, the DDRAM address must be again set after the 8th character is completed. (See Table 13.) Note that the display shift operation is performed for the first and second lines. In the example of Table 13, the display shift is performed when the cursor is on the second line. However, if the shift operation is performed when the cursor is on the first line, both the first and second lines move together. If the shift is repeated, the display of the second line will not move to the first line. The same display will only shift within its own line for the number of times the shift is repeated.

Note: When using the internal reset, the electrical characteristics in the Power Supply Conditions Using Internal Reset Circuit table must be satisfied. If not, the HD44780U must be initialized by instructions. See the section, Initializing by Instruction.

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 Table 11
 8-Bit Operation, 8-Digit  $\times$  1-Line Display Example with Internal Reset

Step					Instr	uction							
No.	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Display	Operation	
1		er supp		the HD	044780	)U is ir	nitialize	d by th	e inte	rnal		Initialized. No display.	
2	Fund 0	tion se	et O	0	1	1	0	0	*	*		Sets to 8-bit operation and selects 1-line display and $5 \times 8$ dot character font. (Number of display lines and character fonts cannot be changed after step #2.)	
3	Disp	ay on/	off con	trol								Turns on display and cursor.	
	0	0	0	0	0	0	1	1	1	0	_	Entire display is in space mode because of initialization.	
4	Entry	/ mode	set									Sets mode to increment the	
	0	0	0	0	0	0	0	1	1	0	_	address by one and to shift the cursor to the right at the time of write to the DD/CGRAM. Display is not shifted.	
5	Write	data t	o CGF	RAM/DI	DRAM						H_	Writes H. DDRAM has already	
	1	0	0	1	0	0	1	0	0	0		been selected by initialization when the power was turned on. The cursor is incremented by one and shifted to the right.	
6	Write	data t	o CGF	RAM/DI	DRAM						HI_	Writes I.	
	1	0	0	1	0	0	1	0	0	1	пі_		
7											· ·		
						•					•		
						•					•		
8	Write 1	data t	o CGF 0	RAM/DI 1	DRAM 0	0	1	0	0	1	HITACHI_	Writes I.	
9	Entry 0	mode 0	set 0	0	0	0	0	1	1	1	HITACHI_	Sets mode to shift display at the time of write.	
10	Write	data t	o CGF	RAM/DI 0	DRAM 1	0	0	0	0	0	ITACHI _	Writes a space.	

Table 11 8-Bit Operation, 8-Digit × 1-Line Display Example with Internal Reset (cont)

Step				Instruction								
No.	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Display	Operation
11	Write	data t	o CGR	AM/DI							TACHI M_	Writes M.
	1	0	0	1	0	0	1	1	0	1	17101 II W_	
12											•	
											•	
						•					•	
13	Write	data t	o CGR	AM/DI	DRAM						Luopovo	Writes O.
	1	0	0	1	0	0	1	1	1	1	MICROKO_	
14	Curs	or or di	isplay s	shift							MICROKO	Shifts only the cursor position
	0	0	0	0	0	1	0	0	*	*	WICKORQ	to the left.
15	Curs	or or di	isplay s	shift							MICRO <u>K</u> O	Shifts only the cursor position
	0	0	0	0	0	1	0	0	*	*	WICKO <u>K</u> O	to the left.
16	Write	data t	o CGR	AM/DI	DRAM						ICROCO	Writes C over K.
	1	0	0	1	0	0	0	0	1	1	ICKOCO	The display moves to the left.
17	Curs	or or di	isplay s	shift							MICROCO	Shifts the display and cursor
	0	0	0	0	0	1	1	1	*	*	WIIGH COO	position to the right.
18	Curs	or or di	isplay s								MICROCO_	Shifts the display and cursor
	0	0	0	0	0	1	0	1	*	*		position to the right.
19		data t									ICROCOM_	Writes M.
	1	0	0	1	0	0	1	1	0	1		
20											•	
						•					•	
21	Retu	rn hom	ie								LUTAOLU	Returns both display and
	0	0	0	0	0	0	0	0	1	0	HITACHI	cursor to the original position
												(address 0).

 Table 12
 4-Bit Operation, 8-Digit × 1-Line Display Example with Internal Reset

Step					Instr	uction		
No.	RS	R/W	DB7	DB6	DB5	DB4	 Display	Operation
1		er supp t circuit	•	the HI	044780	OU is initialized by the internal		Initialized. No display.
2	Fund 0	ction se	et O	0	1	0		Sets to 4-bit operation. In this case, operation is handled as 8 bits by initialization, and only this instruction completes with one write.
3	Fund 0 0	otion se 0 0	et 0 0	0 0	1 *	0 *		Sets 4-bit operation and selects 1-line display and 5 × 8 dot character font. 4-bit operation starts from this step and resetting is necessary. (Number of display lines and character fonts cannot be changed after step #3.)
4		lay on/						Turns on display and cursor.
	0 0	0 0	0 1	0 1	0 1	0	_	<ul><li>Entire display is in space mode because of initialization.</li></ul>
5	Entr	y mode	set					Sets mode to increment the
	0	0	0	0	0	0	_	address by one and to shift the
	0	0	0	1	1	0		cursor to the right at the time of write to the DD/CGRAM. Display is not shifted.
6	Writ	e data t	to CGF	RAM/D	DRAM		Н	Writes H.
	1	0	0	1	0	0	_ · · ·	The cursor is incremented by
	1	0	1	0	0	0		one and shifts to the right.

Note: The control is the same as for 8-bit operation beyond step #6.

 Table 13
 8-Bit Operation, 8-Digit  $\times$  2-Line Display Example with Internal Reset

Step		Instruction										
No.	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Display	Operation
1		er supp t circuit	-	the HE	044780	)U is in	itialize	d by th	ne inte	rnal		Initialized. No display.
2	Fund 0	ction se	t 0	0	1	1	1	0	*	*		Sets to 8-bit operation and selects 2-line display and $5 \times 8$ dot character font.
3	Disp 0	lay on/o	off con	trol 0	0	0	1	1	1	0	_	Turns on display and cursor. All display is in space mode because of initialization.
4	Entry 0	/ mode 0	set 0	0	0	0	0	1	1	0	_	Sets mode to increment the address by one and to shift the cursor to the right at the time of write to the DD/CGRAM. Display is not shifted.
5	Write 1	e data t 0	o CGF 0	RAM/DI 1	DRAM 0	0	1	0	0	0	H_	Writes H. DDRAM has already been selected by initialization when the power was turned on. The cursor is incremented by one and shifted to the right.
6												
7	Write	data t	o CGR	RAM/DI	DRAM 0	0	1	0	0	1	HITACHI_	Writes I.
8	Set I	ODRAN 0	1 addre	ess 1	0	0	0	0	0	0	HITACHI	Sets DDRAM address so that the cursor is positioned at the head of the second line.

 Table 13
 8-Bit Operation, 8-Digit  $\times$  2-Line Display Example with Internal Reset (cont)

Step					Instr	uction						
No.	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Display	Operation
9	Write	data t	o CGR	RAM/DI	DRAM						HITACHI	Writes M.
	1	0	0	1	0	0	1	1	0	1	M_	
10												
						•					•	
						•					•	
						•					•	
											•	
11		data t									HITACHI	Writes O.
	1	0	0	1	0	0	1	1	1	1	MICROCO_	
12	Entry	mode	set								HITACHI	Sets mode to shift display at
	0	0	0	0	0	0	0	1	1	1	MICROCO_	the time of write.
13	Write	data t	o CGR	RAM/DI	DRAM						ITACHI	Writes M. Display is shifted to
	1	0	0	1	0	0	1	1	0	1	ICROCOM_	the left. The first and second lines both shift at the same
												time.
14						•					•	
						•					•	
											•	
15	Retu	rn hom									HITACHI	Returns both display and
	0	0	0	0	0	0	0	0	1	0	MICROCOM	cursor to the original position (address 0).

#### **Initializing by Instruction**

If the power supply conditions for correctly operating the internal reset circuit are not met, initialization by instructions becomes necessary.

Refer to Figures 23 and 24 for the procedures on 8-bit and 4-bit initializations, respectively.

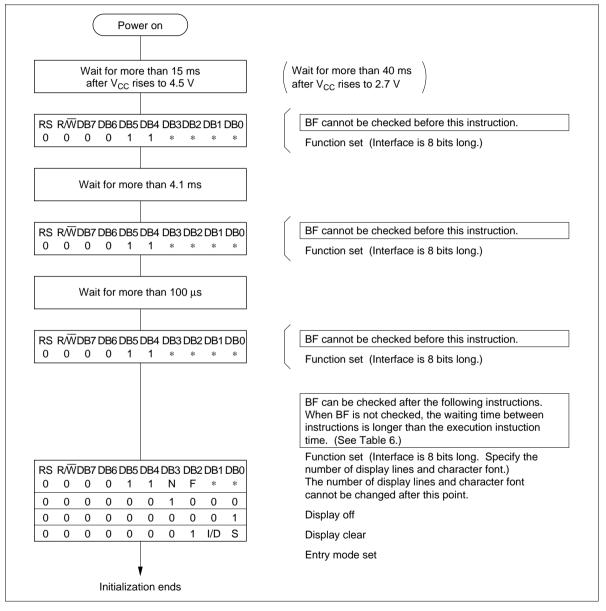


Figure 23 8-Bit Interface

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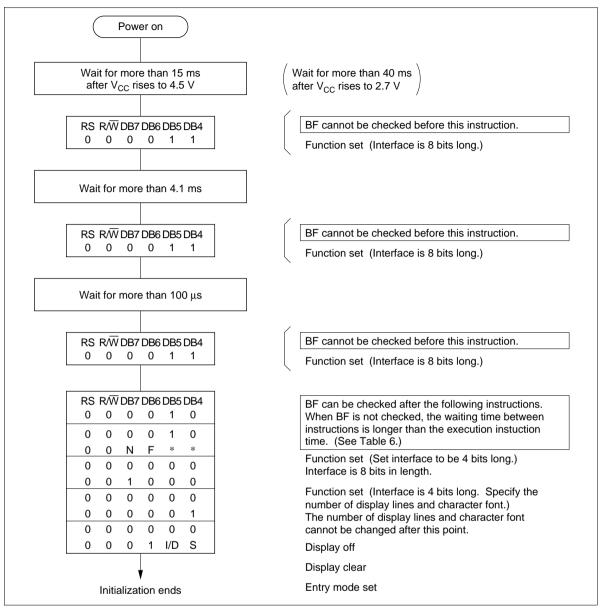


Figure 24 4-Bit Interface

## **Absolute Maximum Ratings\***

Item	Symbol	Value	Unit	Notes
Power supply voltage (1)	V <sub>cc</sub> -GND	-0.3 to +7.0	V	1
Power supply voltage (2)	V <sub>cc</sub> -V5	-0.3 to +13.0	V	1, 2
Input voltage	Vt	–0.3 to $V_{\rm cc}$ +0.3	V	1
Operating temperature	T <sub>opr</sub>	-30 to +75	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	4

Note: \* If the LSI is used above these absolute maximum ratings, it may become permanently damaged. Using the LSI within the following electrical characteristic limits is strongly recommended for normal operation. If these electrical characteristic conditions are also exceeded, the LSI will malfunction and cause poor reliability.

# DC Characteristics (V $_{\rm CC}$ = 2.7 to 4.5 V, $T_{\rm a}$ = –30 to +75°C\*³)

Item	Symbol	Min	Тур	Max	Unit	<b>Test Condition</b>	Notes*
Input high voltage (1) (except OSC1)	VIH1	0.7V <sub>cc</sub>	_	V <sub>cc</sub>	V		6
Input low voltage (1) (except OSC1)	VIL1	-0.3	_	0.55	V		6
Input high voltage (2) (OSC1)	VIH2	0.7V <sub>cc</sub>	_	V <sub>cc</sub>	V		15
Input low voltage (2) (OSC1)	VIL2	_	_	0.2V <sub>cc</sub>	V		15
Output high voltage (1) (DB0–DB7)	VOH1	0.75V <sub>cc</sub>	_	_	V	$-I_{OH} = 0.1 \text{ mA}$	7
Output low voltage (1) (DB0–DB7)	VOL1	_	_	0.2V <sub>CC</sub>	V	I <sub>OL</sub> = 0.1 mA	7
Output high voltage (2) (except DB0–DB7)	VOH2	0.8V <sub>cc</sub>	_	_	V	$-I_{OH} = 0.04 \text{ mA}$	8
Output low voltage (2) (except DB0–DB7)	VOL2	_	_	0.2V <sub>CC</sub>	V	I <sub>OL</sub> = 0.04 mA	8
Driver on resistance (COM)	R <sub>COM</sub>	_	2	20	kΩ	±ld = 0.05 mA, VLCD = 4 V	13
Driver on resistance (SEG)	R <sub>SEG</sub>	_	2	30	kΩ	±ld = 0.05 mA, VLCD = 4 V	13
Input leakage current	I <sub>LI</sub>	<b>-1</b>	_	1	μΑ	VIN = 0 to V <sub>CC</sub>	9
Pull-up MOS current (DB0–DB7, RS, R/W)	$-I_p$	10	50	120	μΑ	$V_{cc} = 3 V$	
Power supply current	I <sub>cc</sub>	_	150	300	μА	$R_f$ oscillation, external clock $V_{cc} = 3 V$ , $f_{osc} = 270 \text{ kHz}$	10, 14
LCD voltage	VLCD1	3.0		11.0	V	V <sub>cc</sub> -V5, 1/5 bias	16
	VLCD2	3.0	_	11.0	V	V <sub>cc</sub> -V5, 1/4 bias	16

Note: \* Refer to the Electrical Characteristics Notes section following these tables.

# AC Characteristics (V $_{\rm CC}$ = 2.7 to 4.5 V, $T_a$ = –30 to +75°C\*³)

#### **Clock Characteristics**

Item		Symbol	Min	Тур	Max	Unit	<b>Test Condition</b>	Note*
External	External clock frequency	f <sub>cp</sub>	125	250	350	kHz		11
clock	External clock duty	Duty	45	50	55	%		
operation	External clock rise time	t <sub>rcp</sub>	_	_	0.2	μs	-	
	External clock fall time	t <sub>fcp</sub>	_	_	0.2	μs	-	
R <sub>f</sub> oscillation	Clock oscillation frequency	f <sub>OSC</sub>	190	270	350	kHz	$R_f = 75 \text{ k}\Omega,$ $V_{CC} = 3 \text{ V}$	12

Note: \* Refer to the Electrical Characteristics Notes section following these tables.

## **Bus Timing Characteristics**

### **Write Operation**

Item	Symbol	Min	Тур	Max	Unit	<b>Test Condition</b>
Enable cycle time	t <sub>cycE</sub>	1000	_	_	ns	Figure 25
Enable pulse width (high level)	$PW_{EH}$	450	_	_		
Enable rise/fall time	t <sub>Er</sub> , t <sub>Ef</sub>	_	_	25		
Address set-up time (RS, R/W to E)	t <sub>AS</sub>	60	_	_		
Address hold time	t <sub>AH</sub>	20	_	_	<del></del>	
Data set-up time	t <sub>DSW</sub>	195	_	_	<del></del>	
Data hold time	t <sub>H</sub>	10	_	_	<del></del>	

#### **Read Operation**

Item	Symbol	Min	Тур	Max	Unit	<b>Test Condition</b>
Enable cycle time	t <sub>cycE</sub>	1000	_	_	ns	Figure 26
Enable pulse width (high level)	PW <sub>EH</sub>	450	_	_		
Enable rise/fall time	t <sub>Er</sub> , t <sub>Ef</sub>	_	_	25		
Address set-up time (RS, $R/\overline{W}$ to E)	t <sub>AS</sub>	60	_	_		
Address hold time	t <sub>AH</sub>	20	_	_		
Data delay time	t <sub>DDR</sub>	_	_	360		
Data hold time	$t_{\text{DHR}}$	5	_	_		

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## **Interface Timing Characteristics with External Driver**

Item		Symbol	Min	Тур	Max	Unit	<b>Test Condition</b>
Clock pulse width	High level	t <sub>cwH</sub>	800	_	_	ns	Figure 27
	Low level	t <sub>CWL</sub>	800	_	_		
Clock set-up time		$t_{\text{CSU}}$	500	_	_		
Data set-up time		t <sub>su</sub>	300	_	_		
Data hold time		$t_{\scriptscriptstyle DH}$	300	_	_		
M delay time		$t_{\scriptscriptstyle DM}$	-1000	_	1000		
Clock rise/fall time		t <sub>ct</sub>	_	_	200		

# **Power Supply Conditions Using Internal Reset Circuit**

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Power supply rise time	t <sub>rcc</sub>	0.1	_	10	ms	Figure 28
Power supply off time	$t_{OFF}$	1	_	_		

# DC Characteristics (V $_{\rm CC}$ = 4.5 to 5.5 V, $T_{\rm a}$ = –30 to +75°C\*3)

Item	Symbol	Min	Тур	Max	Unit	<b>Test Condition</b>	Notes*
Input high voltage (1) (except OSC1)	VIH1	2.2	_	V <sub>cc</sub>	V		6
Input low voltage (1) (except OSC1)	VIL1	-0.3	_	0.6	V		6
Input high voltage (2) (OSC1)	VIH2	V <sub>cc</sub> -1.0	_	V <sub>cc</sub>	V		15
Input low voltage (2) (OSC1)	VIL2	_	_	1.0	V		15
Output high voltage (1) (DB0–DB7)	VOH1	2.4	_	_	V	$-I_{OH} = 0.205 \text{ mA}$	7
Output low voltage (1) (DB0–DB7)	VOL1	_	_	0.4	V	I <sub>OL</sub> = 1.2 mA	7
Output high voltage (2) (except DB0–DB7)	VOH2	0.9 V <sub>cc</sub>	_	_	V	$-I_{OH} = 0.04 \text{ mA}$	8
Output low voltage (2) (except DB0–DB7)	VOL2	_	_	0.1 V <sub>cc</sub>	V	I <sub>OL</sub> = 0.04 mA	8
Driver on resistance (COM)	RCOM	_	2	20	kΩ	±ld = 0.05 mA, VLCD = 4 V	13
Driver on resistance (SEG)	RSEG	_	2	30	kΩ	±ld = 0.05 mA, VLCD = 4 V	13
Input leakage current	ILI	-1	_	1	μΑ	VIN = 0 to V <sub>CC</sub>	9
Pull-up MOS current (DB0–DB7, RS, R/W)	-I <sub>p</sub>	50	125	250	μΑ	V <sub>cc</sub> = 5 V	
Power supply current	I <sub>cc</sub>	_	350	600	μΑ	$R_f$ oscillation, external clock $V_{CC} = 5 V$ , $f_{OSC} = 270 \text{ kHz}$	10, 14
LCD voltage	VLCD1	3.0		11.0	V	V <sub>cc</sub> -V5, 1/5 bias	16
	VLCD2	3.0	_	11.0	V	$V_{\rm CC}$ –V5, 1/4 bias	16

Note: \* Refer to the Electrical Characteristics Notes section following these tables.

# AC Characteristics (V $_{\rm CC}$ = 4.5 to 5.5 V, $T_a$ = –30 to +75°C\*³)

#### **Clock Characteristics**

Item		Symbol	Min	Тур	Max	Unit	<b>Test Condition</b>	Notes*
External	External clock frequency	f <sub>cp</sub>	125	250	350	kHz		11
clock	External clock duty	Duty	45	50	55	%		11
operation	External clock rise time	t <sub>rcp</sub>	_	_	0.2	μs		11
	External clock fall time	t <sub>fcp</sub>	_	_	0.2	μs		11
R <sub>f</sub> oscillation	Clock oscillation frequency	f <sub>osc</sub>	190	270	350	kHz	$R_f = 91 \text{ k}\Omega$ $V_{CC} = 5.0 \text{ V}$	12

Note: \* Refer to the Electrical Characteristics Notes section following these tables.

## **Bus Timing Characteristics**

### **Write Operation**

Item	Symbol	Min	Тур	Max	Unit	<b>Test Condition</b>
Enable cycle time	t <sub>cycE</sub>	500	_	_	ns	Figure 25
Enable pulse width (high level)	PW <sub>EH</sub>	230	_	_		
Enable rise/fall time	t <sub>Er</sub> , t <sub>Ef</sub>	_	_	20		
Address set-up time (RS, R/W to E)	t <sub>AS</sub>	40	_	_		
Address hold time	t <sub>AH</sub>	10	_	_	<del></del>	
Data set-up time	t <sub>DSW</sub>	80	_	_		
Data hold time	t <sub>H</sub>	10	_	_	<del></del>	

#### **Read Operation**

Item	Symbol	Min	Тур	Max	Unit	<b>Test Condition</b>
Enable cycle time	t <sub>cycE</sub>	500	_	_	ns	Figure 26
Enable pulse width (high level)	PW <sub>EH</sub>	230	_	_	<del></del>	
Enable rise/fall time	t <sub>Er</sub> , t <sub>Ef</sub>	_	_	20	<del></del>	
Address set-up time (RS, R/W to E)	t <sub>AS</sub>	40	_	_	<del></del>	
Address hold time	t <sub>AH</sub>	10	_	_	<del></del>	
Data delay time	$t_{DDR}$	_	_	160		
Data hold time	$t_{\text{DHR}}$	5	_	_		

# **Interface Timing Characteristics with External Driver**

Item		Symbol	Min	Тур	Max	Unit	<b>Test Condition</b>
Clock pulse width	High level	t <sub>cwH</sub>	800	_	_	ns	Figure 27
	Low level	t <sub>CWL</sub>	800	_	_		
Clock set-up time		t <sub>CSU</sub>	500	_	_		
Data set-up time		t <sub>su</sub>	300	_	_		
Data hold time		$t_{\scriptscriptstyle DH}$	300	_	_		
M delay time		t <sub>DM</sub>	-1000	_	1000		
Clock rise/fall time		t <sub>ct</sub>	_	_	100	<del></del>	

# **Power Supply Conditions Using Internal Reset Circuit**

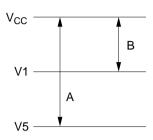
Item	Symbol	Min	Тур	Max	Unit	<b>Test Condition</b>
Power supply rise time	t <sub>rcc</sub>	0.1	_	10	ms	Figure 28
Power supply off time	$t_{OFF}$	1	_	_		

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#### **Electrical Characteristics Notes**

1. All voltage values are referred to GND = 0 V.

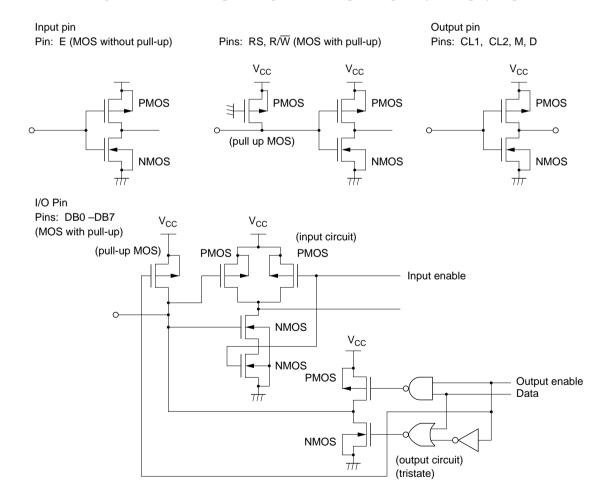


 $A = V_{CC} - V5$   $B = V_{CC} - V1$   $A \ge 1.5 V$ 

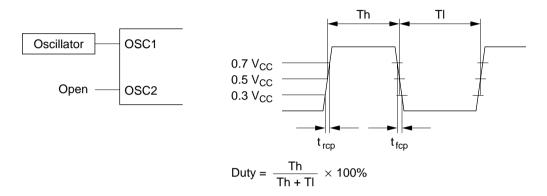
 $B \le 0.25 \times A$ 

The conditions of V1 and V5 voltages are for proper operation of the LSI and not for the LCD output level. The LCD drive voltage condition for the LCD output level is specified as LCD voltage VLCD.

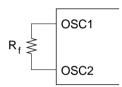
- 2.  $V_{CC} \ge V1 \ge V2 \ge V3 \ge V4 \ge V5$  must be maintained.
- 3. For die products, specified at 75°C.
- 4. For die products, specified by the die shipment specification.
- 5. The following four circuits are I/O pin configurations except for liquid crystal display output.



- 6. Applies to input pins and I/O pins, excluding the OSC1 pin.
- 7. Applies to I/O pins.
- 8. Applies to output pins.
- 9. Current flowing through pull-up MOSs, excluding output drive MOSs.
- 10. Input/output current is excluded. When input is at an intermediate level with CMOS, the excessive current flows through the input circuit to the power supply. To avoid this from happening, the input level must be fixed high or low.
- 11. Applies only to external clock operation.

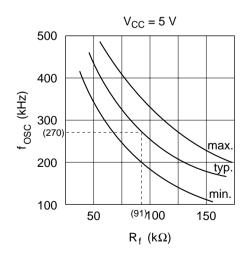


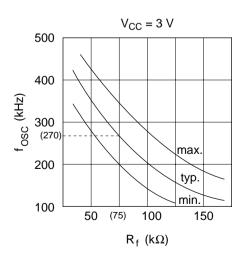
12. Applies only to the internal oscillator operation using oscillation resistor R<sub>f</sub>.



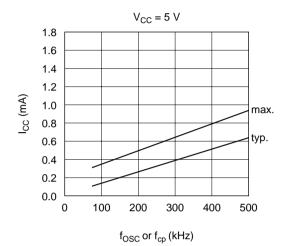
 $R_f$ : 75 k $\Omega$  ± 2% (when  $V_{CC}$  = 3 V)  $R_f$ : 91 k $\Omega$  ± 2% (when  $V_{CC}$  = 5 V)

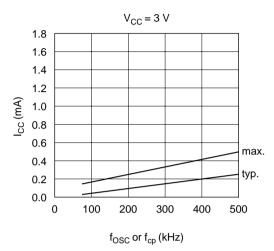
Since the oscillation frequency varies depending on the OSC1 and OSC2 pin capacitance, the wiring length to these pins should be minimized.





- 13. RCOM is the resistance between the power supply pins ( $V_{CC}$ , V1, V4, V5) and each common signal pin (COM1 to COM16).
  - RSEG is the resistance between the power supply pins ( $V_{CC}$ , V2, V3, V5) and each segment signal pin (SEG1 to SEG40).
- 14. The following graphs show the relationship between operation frequency and current consumption.

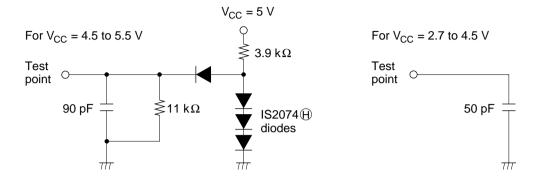




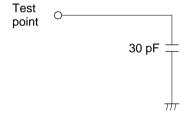
- 15. Applies to the OSC1 pin.
- 16. Each COM and SEG output voltage is within ±0.15 V of the LCD voltage (V<sub>CC</sub>, V1, V2, V3, V4, V5) when there is no load.

## **Load Circuits**

#### Data Bus DB0 to DB7



### External Driver Control Signals: CL1, CL2, D, M



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## **Timing Characteristics**

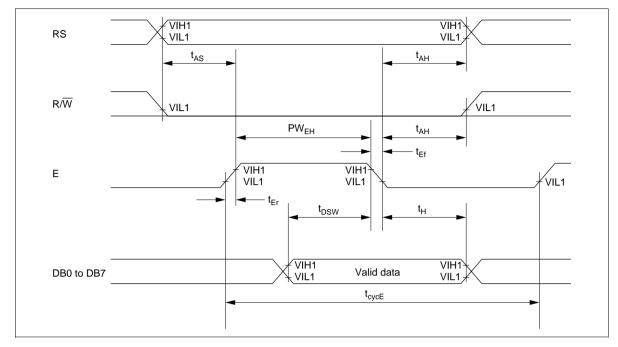


Figure 25 Write Operation

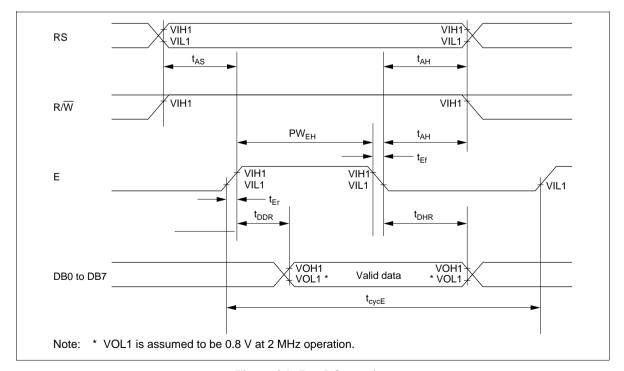


Figure 26 Read Operation

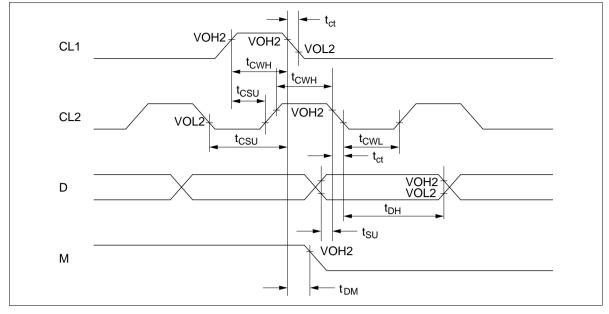
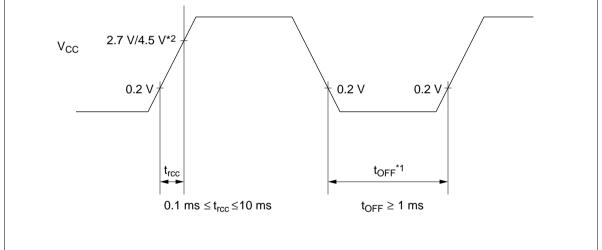


Figure 27 Interface Timing with External Driver



Notes: 1. t<sub>OFF</sub> compensates for the power oscillation period caused by momentary power supply oscillations.

- 2. Specified at 4.5 V for 5-V operation, and at 2.7 V for 3-V operation.
- 3. For if 4.5 V is not reached during 5-V operation, the internal reset circuit will not operate normally.

In this case, the LSI must be initialized by software. (Refer to the Initializing by Instruction section.)

Figure 28 Internal Power Supply Reset

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# **KBL005 - KBL10**

#### **Features**

- · Ideal for printed circuit board .
- Reliable low cost construction.
- High surge current capability.
- UL certified, UL #E96005.



# **Bridge Rectifiers**

## Absolute Maximum Ratings\* T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value							Units
•		005	01	02	04	06	08	10	
$V_{RRM}$	Maximum Repetitive Reverse Voltage	50	100	200	400	600	800	1000	V
V <sub>RMS</sub>	Maximum RMS Bridge Input Voltage	35	70	140	280	420	560	700	V
$V_R$	DC Reverse Voltage (Rated V <sub>R</sub> )	50	100	200	400	600	800	1000	V
I <sub>F(AV)</sub>	Average Rectified Forward Current, @ T <sub>A</sub> = 50°C	4.0							Α
I <sub>FSM</sub>	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave 200					Α			
$T_{stg}$	Storage Temperature Range	-55 to +150					°C		
T <sub>J</sub>	Operating Junction Temperature	-55 to +150						°C	

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

#### **Thermal Characteristics**

Symbol	Parameter	Value	Units
$P_{D}$	Power Dissipation	6.58	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient,* per leg	19	°C/W
R <sub>eJL</sub>	Thermal Resistance, Junction to Lead,* per leg	2.4	°C/W

<sup>\*</sup>Device mounted on PCB with 0.375 " (9.5 mm) lead length and 0.5 x 0.5" (13 x 13 mm) copper pads.

# $\begin{tabular}{ll} \textbf{Electrical Characteristics} & \textbf{T}_{A} = 25 \mbox{°C unless otherwise noted} \\ \end{tabular}$

Symbol	Parameter	Device	Units
$V_{F}$	Forward Voltage, per bridge @ 4.0 A	1.1	V
I <sub>R</sub>	Reverse Current, total bridge @ rated $V_R$ $T_A = 25^{\circ}C$ $T_A = 100^{\circ}C$	5.0 500	μΑ μΑ

# **Bridge Rectifiers**

(continued)

# **Typical Characteristics**

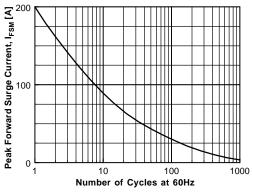


Figure 1. Non-Repetitive Surge Current

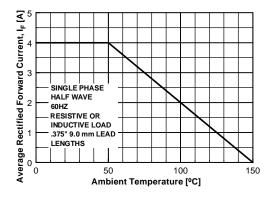


Figure 2. Forward Current Derating Curve

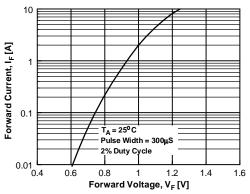


Figure 3. Forward Voltage Characteristics

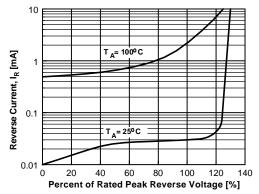


Figure 4. Reverse Current vs Reverse Voltage

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

Rev. H4

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Datasheets for electronics components.



# Low-Power, Slew-Rate-Limited RS-485/RS-422 Transceivers

#### **General Description**

The MAX481, MAX483, MAX485, MAX487–MAX491, and MAX1487 are low-power transceivers for RS-485 and RS-422 communication. Each part contains one driver and one receiver. The MAX483, MAX487, MAX488, and MAX489 feature reduced slew-rate drivers that minimize EMI and reduce reflections caused by improperly terminated cables, thus allowing error-free data transmission up to 250kbps. The driver slew rates of the MAX481, MAX485, MAX490, MAX491, and MAX1487 are not limited, allowing them to transmit up to 2.5Mbps.

These transceivers draw between 120µA and 500µA of supply current when unloaded or fully loaded with disabled drivers. Additionally, the MAX481, MAX483, and MAX487 have a low-current shutdown mode in which they consume only 0.1µA. All parts operate from a single 5V supply.

Drivers are short-circuit current limited and are protected against excessive power dissipation by thermal shutdown circuitry that places the driver outputs into a high-impedance state. The receiver input has a fail-safe feature that guarantees a logic-high output if the input is open circuit.

The MAX487 and MAX1487 feature quarter-unit-load receiver input impedance, allowing up to 128 MAX487/MAX1487 transceivers on the bus. Full-duplex communications are obtained using the MAX488–MAX491, while the MAX481, MAX483, MAX485, MAX487, and MAX1487 are designed for half-duplex applications.

#### **Applications**

Low-Power RS-485 Transceivers
Low-Power RS-422 Transceivers
Level Translators
Transceivers for EMI-Sensitive Applications
Industrial-Control Local Area Networks

#### Next Generation Device Features

- ♦ For Fault-Tolerant Applications
  MAX3430: ±80V Fault-Protected, Fail-Safe, 1/4
  Unit Load, +3.3V, RS-485 Transceiver
  MAX3440E−MAX3444E: ±15kV ESD-Protected,
  ±60V Fault-Protected, 10Mbps, Fail-Safe,
  RS-485/J1708 Transceivers
- ♦ For Space-Constrained Applications MAX3460-MAX3464: +5V, Fail-Safe, 20Mbps, Profibus RS-485/RS-422 Transceivers MAX3362: +3.3V, High-Speed, RS-485/RS-422 Transceiver in a SOT23 Package MAX3280E-MAX3284E: ±15kV ESD-Protected, 52Mbps, +3V to +5.5V, SOT23, RS-485/RS-422, True Fail-Safe Receivers MAX3293/MAX3294/MAX3295: 20Mbps, +3.3V, SOT23, RS-855/RS-422 Transmitters
- ♦ For Multiple Transceiver Applications MAX3030E-MAX3033E: ±15kV ESD-Protected, +3.3V, Quad RS-422 Transmitters
- ♦ For Fail-Safe Applications MAX3080–MAX3089: Fail-Safe, High-Speed (10Mbps), Slew-Rate-Limited RS-485/RS-422 Transceivers
- ♦ For Low-Voltage Applications
  MAX3483E/MAX3485E/MAX3486E/MAX3488E/
  MAX3490E/MAX3491E: +3.3V Powered, ±15kV
  ESD-Protected, 12Mbps, Slew-Rate-Limited,
  True RS-485/RS-422 Transceivers

Ordering Information appears at end of data sheet.

#### **Selection Table**

PART NUMBER	HALF/FULL DUPLEX	DATA RATE (Mbps)	SLEW-RATE LIMITED	LOW-POWER SHUTDOWN	RECEIVER/ DRIVER ENABLE	QUIESCENT CURRENT (µA)	NUMBER OF TRANSMITTERS ON BUS	PIN COUNT
MAX481	Half	2.5	No	Yes	Yes	300	32	8
MAX483	Half	0.25	Yes	Yes	Yes	120	32	8
MAX485	Half	2.5	No	No	Yes	300	32	8
MAX487	Half	0.25	Yes	Yes	Yes	120	128	8
MAX488	Full	0.25	Yes	No	No	120	32	8
MAX489	Full	0.25	Yes	No	Yes	120	32	14
MAX490	Full	2.5	No	No	No	300	32	8
MAX491	Full	2.5	No	No	Yes	300	32	14
MAX1487	Half	2.5	No	No	Yes	230	128	8

MAXIM \_\_\_\_\_\_ Maxim Integrated Products 1

# Low-Power, Slew-Rate-Limited RS-485/RS-422 Transceivers

#### **ABSOLUTE MAXIMUM RATINGS**

Supply Voltage (V <sub>CC</sub> )	12V
Control Input Voltage (RE, DE)	
Driver Input Voltage (DI)	0.5V to $(VCC + 0.5V)$
Driver Output Voltage (A, B)	8V to +12.5V
Receiver Input Voltage (A, B)	8V to +12.5V
Receiver Output Voltage (RO)	0.5V to (V <sub>CC</sub> +0.5V)
Continuous Power Dissipation (T <sub>A</sub> =	+70°C)
8-Pin Plastic DIP (derate 9.09mW/°	C above +70°C)727mW
14-Pin Plastic DIP (derate 10.00mW	/°C above +70°C)800mW
8-Pin SO (derate 5.88mW/°C above	e +70°C)471mW

14-Pin SO (derate 8.33mW/°C above +70°C)
Operating Temperature Ranges
MAX4C/MAX1487C_A0°C to +70°C
MAX4E/MAX1487E_ A40°C to +85°C
MAX4MJ_/MAX1487MJA55°C to +125°C
Storage Temperature Range65°C to +160°C
Lead Temperature (soldering, 10sec)+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = 5V \pm 5\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.})$  (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Differential Driver Output (no load)	Vod1					5	V
Differential Driver Output	1/000	$R = 50\Omega (RS-422)$	2			V	
(with load)	VOD2	$R = 27\Omega$ (RS-485), Figure 4	$R = 27\Omega$ (RS-485), Figure 4			5	V
Change in Magnitude of Driver Differential Output Voltage for Complementary Output States	ΔVOD	$R = 27\Omega$ or $50\Omega$ , Figure 4				0.2	V
Driver Common-Mode Output Voltage	Voc	$R = 27\Omega$ or $50\Omega$ , Figure 4				3	V
Change in Magnitude of Driver Common-Mode Output Voltage for Complementary Output States	ΔVOD	R = $27\Omega$ or $50\Omega$ , Figure 4				0.2	V
Input High Voltage	VIH	DE, DI, RE		2.0			V
Input Low Voltage	V <sub>IL</sub>	DE, DI, RE				0.8	V
Input Current	liN1	DE, DI, RE				±2	μΑ
	I <sub>IN2</sub>	DE = 0V; V <sub>CC</sub> = 0V or 5.25V,	V <sub>IN</sub> = 12V			1.0	mA mA
Input Current (A, B)		all devices except MAX487/MAX1487	V <sub>IN</sub> = -7V			-0.8	
		MAX487/MAX1487, DE = 0V, V <sub>CC</sub> = 0V or 5.25V	V <sub>IN</sub> = 12V			0.25	
			VIN = -7V			-0.2	
Receiver Differential Threshold Voltage	V <sub>TH</sub>	-7V ≤ V <sub>CM</sub> ≤ 12V		-0.2		0.2	V
Receiver Input Hysteresis	ΔVTH	V <sub>CM</sub> = 0V			70		mV
Receiver Output High Voltage	Voн	I <sub>O</sub> = -4mA, V <sub>ID</sub> = 200mV		3.5			V
Receiver Output Low Voltage	VoL	I <sub>O</sub> = 4mA, V <sub>ID</sub> = -200mV				0.4	V
Three-State (high impedance) Output Current at Receiver	lozr	0.4V ≤ V <sub>O</sub> ≤ 2.4V				±1	μA
Receiver Input Resistance	RIN	-7V ≤ V <sub>CM</sub> ≤ 12V, all devices except MAX487/MAX1487		12			kΩ
Trocoiver imput tresistance	1 111/1	-7V ≤ V <sub>CM</sub> ≤ 12V, MAX487/MA	48			kΩ	

2 \_\_\_\_\_\_ MAXIM

# Low-Power, Slew-Rate-Limited RS-485/RS-422 Transceivers

#### DC ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = 5V \pm 5\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.})$  (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS			MIN	TYP	MAX	UNITS
	Icc	MAX488/MAX489, DE, DI, $\overline{RE}$ = 0V or V <sub>C</sub> (	0			120	250	
		MAX490/MAX491, DE, DI, RE = 0V or V <sub>CC</sub>			300	500		
No. Lood Cupply Current		MAX481/MAX485,	DE = V <sub>C</sub> C			500	900	μA
No-Load Supply Current (Note 3)		$\overline{RE} = 0V \text{ or } V_{CC}$	DE = 0V	= 0V		300	500	
(11111111111111111111111111111111111111		MAX1487, RE = 0V or V <sub>CC</sub>	DE = Vcc			300	500	
			DE = 0V			230	400	7
		MAX483/MAX487, RE = 0V or VCC	DE = 5V	MAX483		350	650	
			DL = 5V	MAX487		250	400	
			DE = 0V			120	250	
Supply Current in Shutdown	ISHDN	MAX481/483/487, DE = 0V, RE = V <sub>CC</sub>				0.1	10	μΑ
Driver Short-Circuit Current, Vo = High	I <sub>OSD1</sub>	-7V ≤ V <sub>O</sub> ≤12V (Note 4)			35		250	mA
Driver Short-Circuit Current, VO = Low	l <sub>OSD2</sub>	-7V ≤ V <sub>O</sub> ≤12V (Note 4)			35		250	mA
Receiver Short-Circuit Current	Iosr	0V ≤ VO ≤ VCC			7		95	mA

#### SWITCHING CHARACTERISTICS—MAX481/MAX485, MAX490/MAX491, MAX1487

(V<sub>CC</sub> = 5V  $\pm$ 5%, T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>, unless otherwise noted.) (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Driver Input to Output	tplH	Figures 6 and 8, $R_{DIFF}$ = $54\Omega$ , $C_{L1}$ = $C_{L2}$ = 100pF		10	30	60	- ns
Driver input to Output	tphL			10	30	60	
Driver Output Skew to Output	tskew	Figures 6 and 8, RD	$_{\text{IFF}} = 54\Omega, C_{\text{L1}} = C_{\text{L2}} = 100 \text{pF}$		5	10	ns
	t <sub>R</sub> , t <sub>F</sub>	Figures 6 and 8, $R_{DIFF} = 54\Omega$ , $C_{L1} = C_{L2} = 100pF$	MAX481, MAX485, MAX1487	3	15	40	ns
Driver Rise or Fall Time			MAX490C/E, MAX491C/E	5	15	25	
			MAX490M, MAX491M	3	15	40	
Driver Enable to Output High	tzH	Figures 7 and 9, C	Figures 7 and 9, C <sub>L</sub> = 100pF, S2 closed			70	ns
Driver Enable to Output Low	tzL	Figures 7 and 9, C	L = 100pF, S1 closed		40	70	ns
Driver Disable Time from Low	tLZ	Figures 7 and 9, C <sub>L</sub> = 15pF, S1 closed			40	70	ns
Driver Disable Time from High	tHZ	Figures 7 and 9, C		40	70	ns	
	tplh, tphl		MAX481, MAX485, MAX1487	20	90	200	ns
Receiver Input to Output			MAX490C/E, MAX491C/E	20	90	150	
			MAX490M, MAX491M	20	90	200	
			13		ns		
Receiver Enable to Output Low	tzı.	Figures 5 and 11, CRL = 15pF, S1 closed			20	50	ns
Receiver Enable to Output High	tzH	Figures 5 and 11, C <sub>RL</sub> = 15pF, S2 closed			20	50	ns
Receiver Disable Time from Low		Figures 5 and 11, C <sub>RL</sub> = 15pF, S1 closed			20	50	ns
Receiver Disable Time from High	tHZ	Figures 5 and 11, C <sub>RL</sub> = 15pF, S2 closed			20	50	ns
Maximum Data Rate	fMAX	right to the right of the right		2.5			Mbps
Time to Shutdown	tshdn	MAX481 (Note 5)		50	200	600	ns

#### SWITCHING CHARACTERISTICS—MAX481/MAX485, MAX490/MAX491, MAX1487 (continued)

( $V_{CC} = 5V \pm 5\%$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted.) (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Driver Enable from Shutdown to Output High (MAX481)	tzh(SHDN)	Figures 7 and 9, C <sub>L</sub> = 100pF, S2 closed		40	100	ns
Driver Enable from Shutdown to Output Low (MAX481)	tzL(SHDN)	Figures 7 and 9, C <sub>L</sub> = 100pF, S1 closed		40	100	ns
Receiver Enable from Shutdown to Output High (MAX481)	tzh(SHDN)	Figures 5 and 11, C <sub>L</sub> = 15pF, S2 closed, A - B = 2V		300	1000	ns
Receiver Enable from Shutdown to Output Low (MAX481)	tzL(SHDN)	Figures 5 and 11, C <sub>L</sub> = 15pF, S1 closed, B - A = 2V		300	1000	ns

#### SWITCHING CHARACTERISTICS—MAX483, MAX487/MAX488/MAX489

 $(V_{CC} = 5V \pm 5\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.})$  (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Driver Input to Output	tpLH	Figures 6 and 8, $R_{DIFF} = 54\Omega$ ,	250	800	2000	20
Driver Input to Output	tphl	$C_{L1} = C_{L2} = 100pF$	250	800	2000	ns
Driver Output Skew to Output	tskew	Figures 6 and 8, RDIFF = $54\Omega$ , CL1 = CL2 = $100$ pF		100	800	ns
Driver Rise or Fall Time	t <sub>R</sub> , t <sub>F</sub>	Figures 6 and 8, $R_{DIFF}$ = $54\Omega$ , $C_{L1}$ = $C_{L2}$ = $100pF$	250		2000	ns
Driver Enable to Output High	tzн	Figures 7 and 9, C <sub>L</sub> = 100pF, S2 closed	250		2000	ns
Driver Enable to Output Low	tzL	Figures 7 and 9, C <sub>L</sub> = 100pF, S1 closed	250		2000	ns
Driver Disable Time from Low	tLZ	Figures 7 and 9, C <sub>L</sub> = 15pF, S1 closed	300		3000	ns
Driver Disable Time from High	tHZ	Figures 7 and 9, C <sub>L</sub> = 15pF, S2 closed	300		3000	ns
Descriver land to Outrout	tpLH	Figures 6 and 10, $R_{DIFF} = 54\Omega$ ,	250		2000	
Receiver Input to Output	tphL	$C_{L1} = C_{L2} = 100pF$	250		2000 ns	
I t <sub>PLH</sub> - t <sub>PHL</sub> I Differential Receiver Skew	tskd	Figures 6 and 10, RDIFF = $54\Omega$ , $C_{L1} = C_{L2} = 100$ pF		100		ns
Receiver Enable to Output Low	tzL	Figures 5 and 11, C <sub>RL</sub> = 15pF, S1 closed		20	50	ns
Receiver Enable to Output High	tzH	Figures 5 and 11, C <sub>RL</sub> = 15pF, S2 closed		20	50	ns
Receiver Disable Time from Low	tLZ	Figures 5 and 11, C <sub>RL</sub> = 15pF, S1 closed		20	50	ns
Receiver Disable Time from High	tHZ	Figures 5 and 11, C <sub>RL</sub> = 15pF, S2 closed		20	50	ns
Maximum Data Rate	fMAX	tplh, tphl < 50% of data period	250			kbps
Time to Shutdown	tshdn	MAX483/MAX487 (Note 5)	50	200	600	ns
Driver Enable from Shutdown to Output High	tzh(SHDN)	MAX483/MAX487, Figures 7 and 9, C <sub>L</sub> = 100pF, S2 closed			2000	ns
Driver Enable from Shutdown to Output Low	tzL(SHDN)	MAX483/MAX487, Figures 7 and 9, C <sub>L</sub> = 100pF, S1 closed			2000	ns
Receiver Enable from Shutdown to Output High	tzh(SHDN)	MAX483/MAX487, Figures 5 and 11, C <sub>L</sub> = 15pF, S2 closed			2500	ns
Receiver Enable from Shutdown to Output Low	tzL(SHDN)	MAX483/MAX487, Figures 5 and 11, C <sub>L</sub> = 15pF, S1 closed			2500	ns

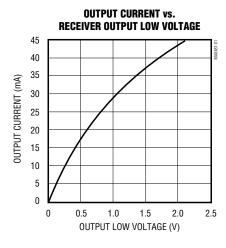
4 \_\_\_\_\_\_ M/1XI/NI

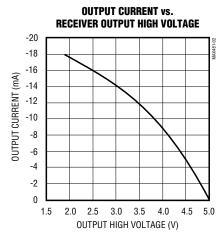
#### NOTES FOR ELECTRICAL/SWITCHING CHARACTERISTICS

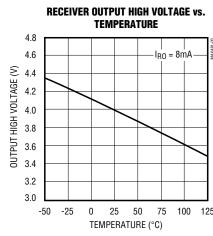
- **Note 1:** All currents into device pins are positive; all currents out of device pins are negative. All voltages are referenced to device ground unless otherwise specified.
- **Note 2:** All typical specifications are given for  $V_{CC} = 5V$  and  $T_A = +25^{\circ}C$ .
- **Note 3:** Supply current specification is valid for loaded transmitters when DE = 0V.
- Note 4: Applies to peak current. See Typical Operating Characteristics.
- Note 5: The MAX481/MAX483/MAX487 are put into shutdown by bringing RE high and DE low. If the inputs are in this state for less than 50ns, the parts are guaranteed not to enter shutdown. If the inputs are in this state for at least 600ns, the parts are guaranteed to have entered shutdown. See Low-Power Shutdown Mode section.

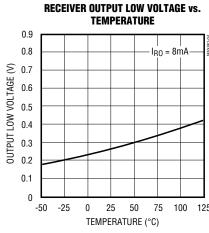
### \_Typical Operating Characteristics

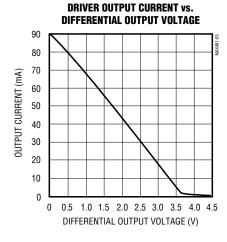
( $V_{CC} = 5V$ ,  $T_A = +25$ °C, unless otherwise noted.)

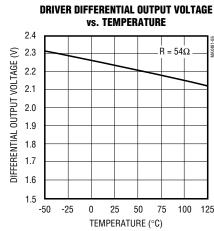






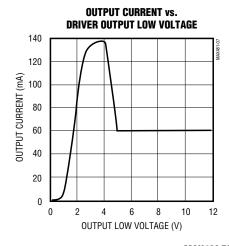


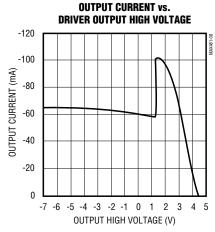


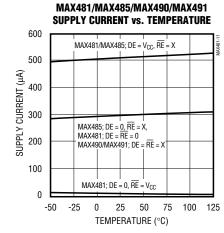


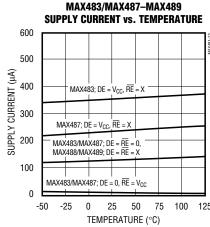
### \_Typical Operating Characteristics (continued)

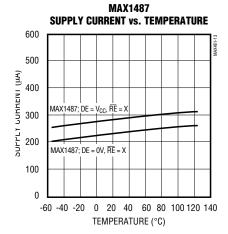
 $(V_{CC} = 5V, T_A = +25^{\circ}C, unless otherwise noted.)$ 











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#### **Pin Description**

PIN		PIN		PIN MAX481/MAX483/ MAX485/MAX487/ MAX1487  MAX488/ MAX490  MAX491			
MAX485/	MAX487/		NAME			FUNCTION	
DIP/SO	μМΑХ	DIP/SO	μМΑХ	DIP/SO			
1	3	2	4	2	RO	Receiver Output: If A > B by 200mV, RO will be high; If A < B by 200mV, RO will be low.	
2	4	_	_	3	RE	Receiver Output Enable. RO is enabled when $\overline{\text{RE}}$ is low; RO is high impedance when $\overline{\text{RE}}$ is high.	
3	5	_	_	4	DE	Driver Output Enable. The driver outputs, Y and Z, are enabled by bringing DE high. They are high impedance when DE is low. If the driver outputs are enabled, the parts function as line drivers. While they are high impedance, they function as line receivers if RE is low.	
4	6	3	5	5	DI	Driver Input. A low on DI forces output Y low and output Z high. Similarly, a high on DI forces output Y high and output Z low.	
5	7	4	6	6, 7	GND	Ground	
_	_	5	7	9	Υ	Noninverting Driver Output	
_	_	6	8	10	Z	Inverting Driver Output	
6	8	_	_	_	А	Noninverting Receiver Input and Noninverting Driver Output	
_	_	8	2	12	А	Noninverting Receiver Input	
7	1	_	_	_	В	Inverting Receiver Input and Inverting Driver Output	
_	_	7	1	11	В	Inverting Receiver Input	
8	2	1	3	14	Vcc	Positive Supply: 4.75V ≤ V <sub>CC</sub> ≤ 5.25V	
_	_	_	_	1, 8, 13	N.C.	No Connect—not internally connected	

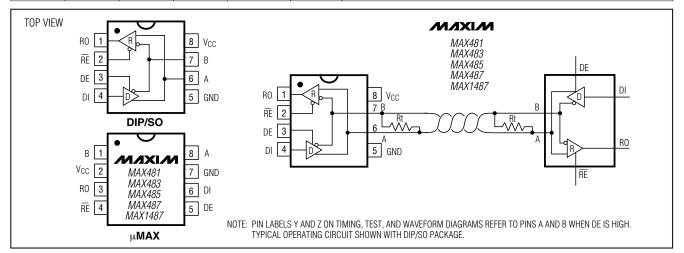


Figure 1. MAX481/MAX483/MAX485/MAX487/MAX1487 Pin Configuration and Typical Operating Circuit

/VI/IXI/VI \_\_\_\_

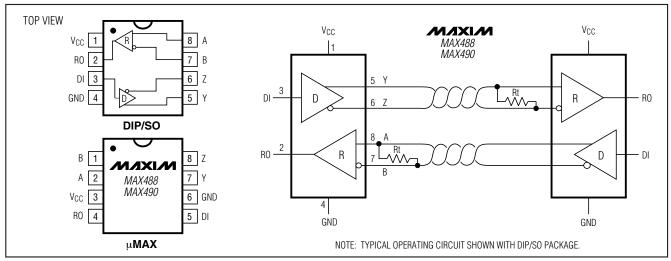


Figure 2. MAX488/MAX490 Pin Configuration and Typical Operating Circuit

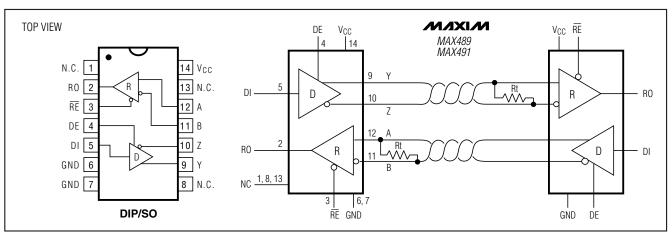


Figure 3. MAX489/MAX491 Pin Configuration and Typical Operating Circuit

# Applications Information

The MAX481/MAX483/MAX485/MAX487–MAX491 and MAX1487 are low-power transceivers for RS-485 and RS-422 communications. The MAX481, MAX485, MAX490, MAX491, and MAX1487 can transmit and receive at data rates up to 2.5Mbps, while the MAX483, MAX487, MAX488, and MAX489 are specified for data rates up to 250kbps. The MAX488–MAX491 are full-duplex transceivers while the MAX481, MAX483, MAX485, MAX487, and MAX1487 are half-duplex. In addition, Driver Enable (DE) and Receiver Enable (RE) pins are included on the MAX481, MAX483, MAX485, MAX487, MAX489, MAX491, and MAX1487. When disabled, the driver and receiver outputs are high impedance.

# MAX487/MAX1487: 128 Transceivers on the Bus

The  $48k\Omega$ , 1/4-unit-load receiver input impedance of the MAX487 and MAX1487 allows up to 128 transceivers on a bus, compared to the 1-unit load ( $12k\Omega$  input impedance) of standard RS-485 drivers (32 transceivers maximum). Any combination of MAX487/MAX1487 and other RS-485 transceivers with a total of 32 unit loads or less can be put on the bus. The MAX481/MAX483/MAX485 and MAX488–MAX491 have standard  $12k\Omega$  Receiver Input impedance.

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**Test Circuits** 

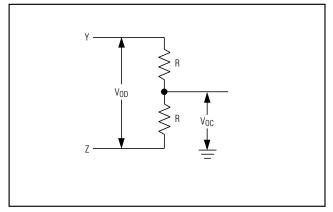


Figure 4. Driver DC Test Load

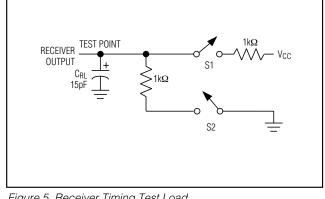


Figure 5. Receiver Timing Test Load

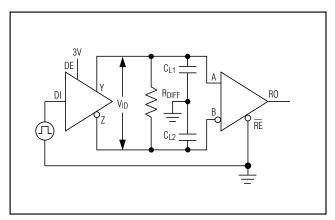


Figure 6. Driver/Receiver Timing Test Circuit

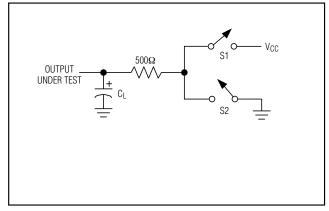


Figure 7. Driver Timing Test Load

#### MAX483/MAX487/MAX488/MAX489: **Reduced EMI and Reflections**

The MAX483 and MAX487-MAX489 are slew-rate limited, minimizing EMI and reducing reflections caused by improperly terminated cables. Figure 12 shows the driver output waveform and its Fourier analysis of a 150kHz signal transmitted by a MAX481, MAX485, MAX490, MAX491, or MAX1487. High-frequency harmonics with large amplitudes are evident. Figure 13 shows the same information displayed for a MAX483. MAX487, MAX488, or MAX489 transmitting under the same conditions. Figure 13's high-frequency harmonics have much lower amplitudes, and the potential for EMI is significantly reduced.

#### Switching Waveforms

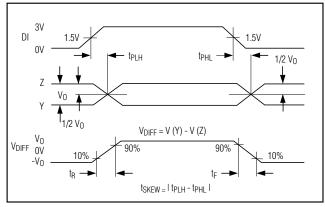


Figure 8. Driver Propagation Delays

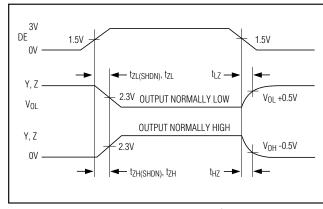


Figure 9. Driver Enable and Disable Times (except MAX488 and MAX490)

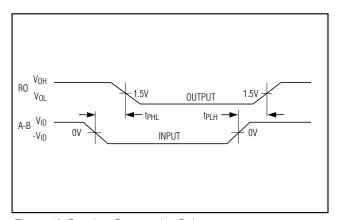


Figure 10. Receiver Propagation Delays

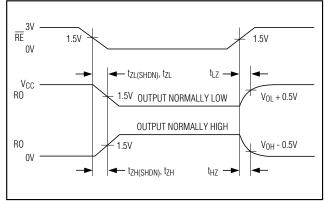


Figure 11. Receiver Enable and Disable Times (except MAX488 and MAX490)

### Function Tables (MAX481/MAX483/MAX485/MAX487/MAX1487)

#### **Table 1. Transmitting**

	INPUTS	OUTPUTS			
RE	DE	DI	Z	Y	
X	1	1	0	1	
X	1	0	1	0	
0	0	Х	High-Z	High-Z	
1	0	Х	High-Z*	High-Z*	

X = Don't care

High-Z = High impedance

\* Shutdown mode for MAX481/MAX483/MAX487

#### Table 2. Receiving

	INPUTS					
RE	DE	A-B	RO			
0	0	≥ +0.2V	1			
0	0	≤ -0.2V	0			
0	0	Inputs open	1			
1	0	X	High-Z*			

X = Don't care

High-Z = High impedance

\* Shutdown mode for MAX481/MAX483/MAX487

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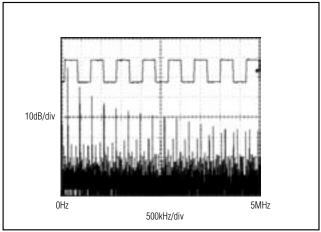


Figure 12. Driver Output Waveform and FFT Plot of MAX481/ MAX485/MAX490/MAX491/MAX1487 Transmitting a 150kHz Signal

# Low-Power Shutdown Mode (MAX481/MAX483/MAX487)

A low-power shutdown mode is initiated by bringing both  $\overline{RE}$  high and DE low. The devices will not shut down unless both the driver and receiver are disabled. In shutdown, the devices typically draw only 0.1 $\mu$ A of supply current.

 $\overline{\text{RE}}$  and DE may be driven simultaneously; the parts are guaranteed not to enter shutdown if  $\overline{\text{RE}}$  is high and DE is low for less than 50ns. If the inputs are in this state for at least 600ns, the parts are guaranteed to enter shutdown.

For the MAX481, MAX483, and MAX487, the tZH and tZL enable times assume the part was not in the low-power shutdown state (the MAX485/MAX488–MAX491 and MAX1487 can not be shut down). The tZH(SHDN) and tZL(SHDN) enable times assume the parts were shut down (see *Electrical Characteristics*).

It takes the drivers and receivers longer to become enabled from the low-power shutdown state (tzh(shdn), tzl(shdn)) than from the operating mode (tzh, tzl). (The parts are in operating mode if the  $\overline{\text{RE}}$ , DE inputs equal a logical 0,1 or 1,1 or 0, 0.)

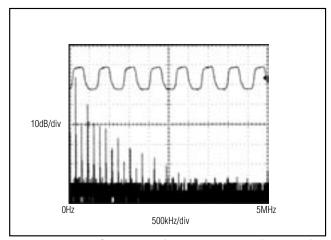


Figure 13. Driver Output Waveform and FFT Plot of MAX483/ MAX487–MAX489 Transmitting a 150kHz Signal

#### **Driver Output Protection**

Excessive output current and power dissipation caused by faults or by bus contention are prevented by two mechanisms. A foldback current limit on the output stage provides immediate protection against short circuits over the whole common-mode voltage range (see *Typical Operating Characteristics*). In addition, a thermal shutdown circuit forces the driver outputs into a high-impedance state if the die temperature rises excessively.

#### **Propagation Delay**

Many digital encoding schemes depend on the difference between the driver and receiver propagation delay times. Typical propagation delays are shown in Figures 15–18 using Figure 14's test circuit.

The difference in receiver delay times, I tp<sub>LH</sub> - tp<sub>HL</sub> I, is typically under 13ns for the MAX481, MAX485, MAX490, MAX491, and MAX1487 and is typically less than 100ns for the MAX483 and MAX487–MAX489.

The driver skew times are typically 5ns (10ns max) for the MAX481, MAX485, MAX490, MAX491, and MAX1487, and are typically 100ns (800ns max) for the MAX483 and MAX487–MAX489.

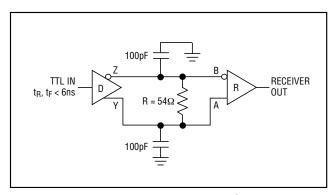


Figure 14. Receiver Propagation Delay Test Circuit

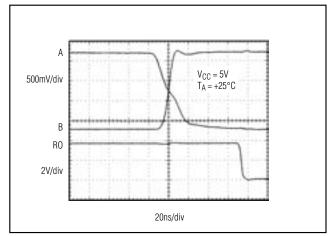


Figure 15. MAX481/MAX485/MAX490/MAX491/MAX1487 Receiver tpHL

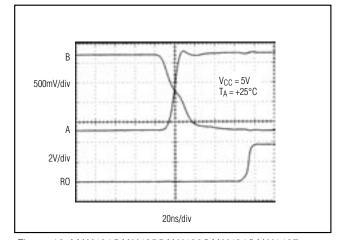


Figure 16. MAX481/MAX485/MAX490/MAX491/MAX1487 Receiver t<sub>PLH</sub>

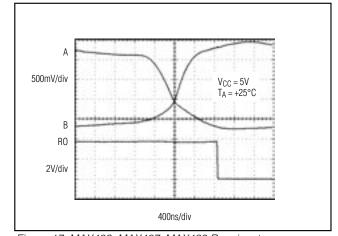


Figure 17. MAX483, MAX487-MAX489 Receiver tPHL

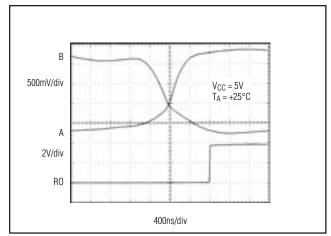


Figure 18. MAX483, MAX487-MAX489 Receiver tPLH

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#### Line Length vs. Data Rate

The RS-485/RS-422 standard covers line lengths up to 4000 feet. For line lengths greater than 4000 feet, see Figure 23.

Figures 19 and 20 show the system differential voltage for the parts driving 4000 feet of 26AWG twisted-pair wire at 110kHz into  $120\Omega$  loads.

#### **Typical Applications**

The MAX481, MAX483, MAX485, MAX487–MAX491, and MAX1487 transceivers are designed for bidirectional data communications on multipoint bus transmission lines.

Figures 21 and 22 show typical network applications circuits. These parts can also be used as line repeaters, with cable lengths longer than 4000 feet, as shown in Figure 23.

To minimize reflections, the line should be terminated at both ends in its characteristic impedance, and stub lengths off the main line should be kept as short as possible. The slew-rate-limited MAX483 and MAX487–MAX489 are more tolerant of imperfect termination.

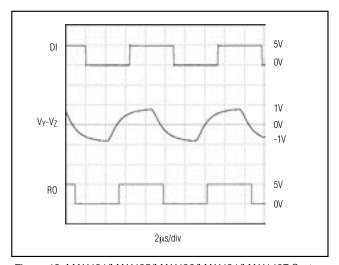


Figure 19. MAX481/MAX485/MAX490/MAX491/MAX1487 System Differential Voltage at 110kHz Driving 4000ft of Cable

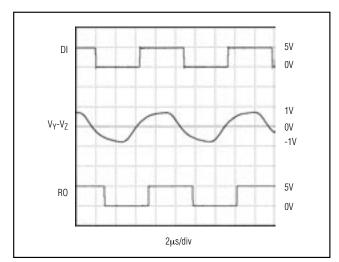


Figure 20. MAX483, MAX487–MAX489 System Differential Voltage at 110kHz Driving 4000ft of Cable

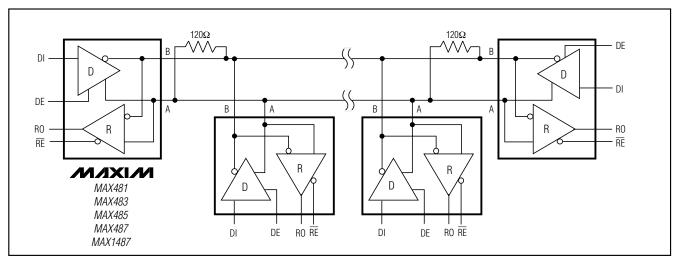


Figure 21. MAX481/MAX483/MAX485/MAX487/MAX1487 Typical Half-Duplex RS-485 Network

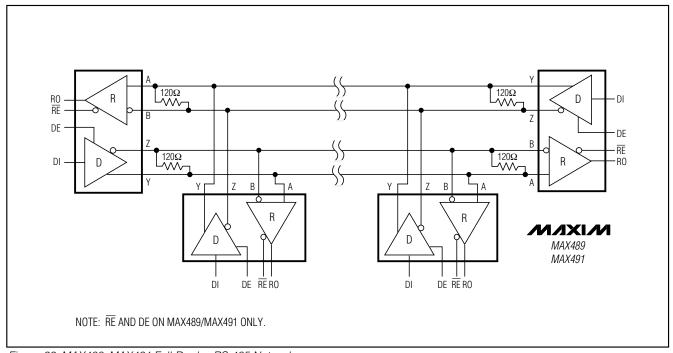


Figure 22. MAX488-MAX491 Full-Duplex RS-485 Network

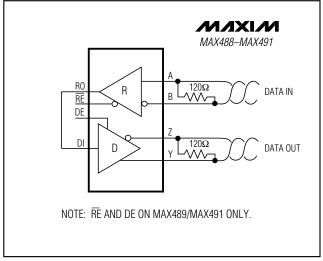


Figure 23. Line Repeater for MAX488-MAX491

#### **Isolated RS-485**

For isolated RS-485 applications, see the MAX253 and MAX1480 data sheets.

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### **Ordering Information**

PART	TEMP. RANGE	PIN-PACKAGE
MAX481CPA	0°C to +70°C	8 Plastic DIP
MAX481CSA	0°C to +70°C	8 SO
MAX481CUA	0°C to +70°C	8 μMAX
MAX481C/D	0°C to +70°C	Dice*
MAX481EPA	-40°C to +85°C	8 Plastic DIP
MAX481ESA	-40°C to +85°C	8 SO
MAX481MJA	-55°C to +125°C	8 CERDIP
MAX483CPA	0°C to +70°C	8 Plastic DIP
MAX483CSA	0°C to +70°C	8 SO
MAX483CUA	0°C to +70°C	8 μMAX
MAX483C/D	0°C to +70°C	Dice*
MAX483EPA	-40°C to +85°C	8 Plastic DIP
MAX483ESA	-40°C to +85°C	8 SO
MAX483MJA	-55°C to +125°C	8 CERDIP
MAX485CPA	0°C to +70°C	8 Plastic DIP
MAX485CSA	0°C to +70°C	8 SO
MAX485CUA	0°C to +70°C	8 μMAX
MAX485C/D	0°C to +70°C	Dice*
MAX485EPA	-40°C to +85°C	8 Plastic DIP
MAX485ESA	-40°C to +85°C	8 SO
MAX485MJA	-55°C to +125°C	8 CERDIP
MAX487CPA	0°C to +70°C	8 Plastic DIP
MAX487CSA	0°C to +70°C	8 SO
MAX487CUA	0°C to +70°C	8 μMAX
MAX487C/D	0°C to +70°C	Dice*
MAX487EPA	-40°C to +85°C	8 Plastic DIP
MAX487ESA	-40°C to +85°C	8 SO
MAX487MJA	-55°C to +125°C	8 CERDIP
MAX488CPA	0°C to +70°C	8 Plastic DIP
MAX488CSA	0°C to +70°C	8 SO
MAX488CUA	0°C to +70°C	8 μMAX
MAX488C/D	0°C to +70°C	Dice*
MAX488EPA	-40°C to +85°C	8 Plastic DIP
MAX488ESA	-40°C to +85°C	8 SO
MAX488MJA	-55°C to +125°C	8 CERDIP
MAX489CPD	0°C to +70°C	14 Plastic DIP
MAX489CSD	0°C to +70°C	14 SO
MAX489C/D	0°C to +70°C	Dice*
MAX489EPD	-40°C to +85°C	14 Plastic DIP
MAX489ESD	-40°C to +85°C	14 SO
MAX489MJD	-55°C to +125°C	14 CERDIP

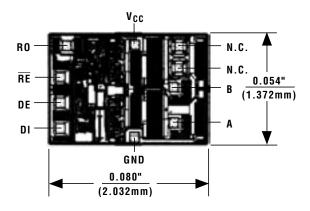
### \_Ordering Information (continued)

PART	TEMP. RANGE	PIN-PACKAGE
MAX490CPA	0°C to +70°C	8 Plastic DIP
MAX490CSA	0°C to +70°C	8 SO
MAX490CUA	0°C to +70°C	8 μMAX
MAX490C/D	0°C to +70°C	Dice*
MAX490EPA	-40°C to +85°C	8 Plastic DIP
MAX490ESA	-40°C to +85°C	8 SO
MAX490MJA	-55°C to +125°C	8 CERDIP
MAX491CPD	0°C to +70°C	14 Plastic DIP
MAX491CSD	0°C to +70°C	14 SO
MAX491C/D	0°C to +70°C	Dice*
MAX491EPD	-40°C to +85°C	14 Plastic DIP
MAX491ESD	-40°C to +85°C	14 SO
MAX491MJD	-55°C to +125°C	14 CERDIP
MAX1487CPA	0°C to +70°C	8 Plastic DIP
MAX1487CSA	0°C to +70°C	8 SO
MAX1487CUA	0°C to +70°C	8 μMAX
MAX1487C/D	0°C to +70°C	Dice*
MAX1487EPA	-40°C to +85°C	8 Plastic DIP
MAX1487ESA	-40°C to +85°C	8 SO
MAX1487MJA	-55°C to +125°C	8 CERDIP

<sup>\*</sup> Contact factory for dice specifications.

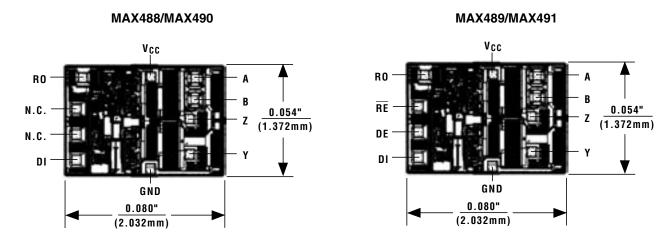
## **Chip Topographies**

#### MAX481/MAX483/MAX485/MAX487/MAX1487



*M/XI/M* \_\_\_\_\_\_ 15

### **Chip Topographies (continued)**

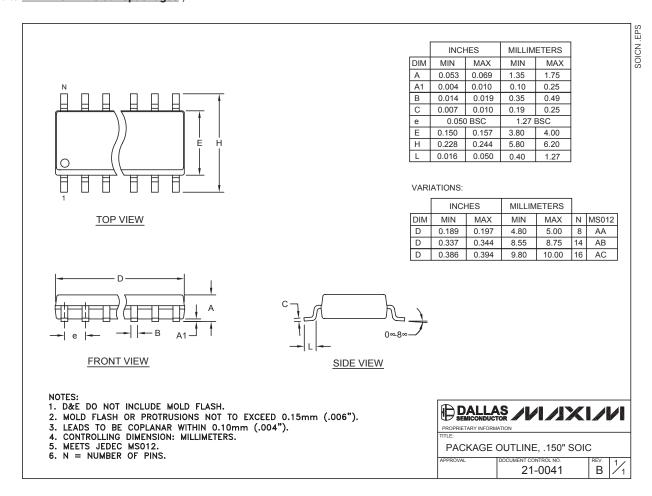


TRANSISTOR COUNT: 248
SUBSTRATE CONNECTED TO GND

16 \_\_\_\_\_\_ MAXIM

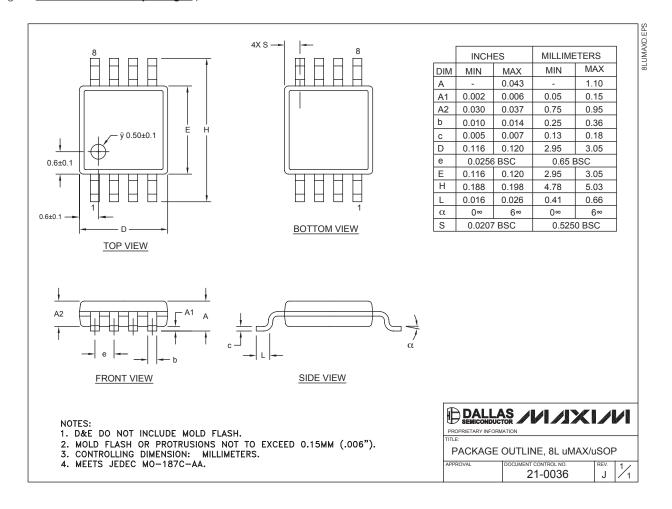
#### Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



#### **Package Information (continued)**

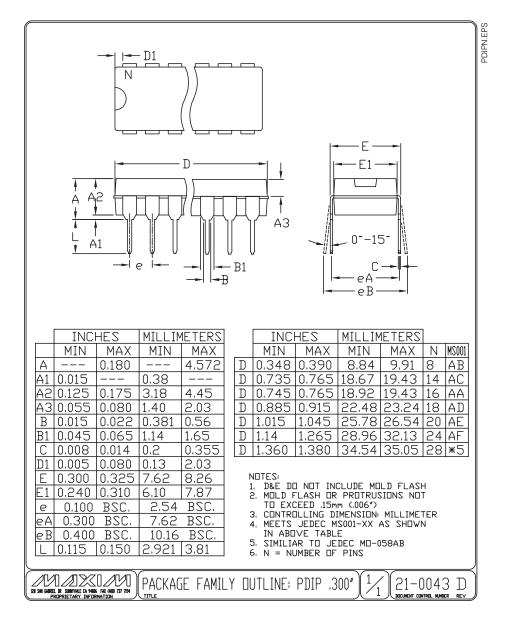
(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



18 \_\_\_\_\_\_ MAXIM

#### Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



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MAX481/MAX483/MAX485/MAX487-MAX49<sup>.</sup>



# MC78TXX

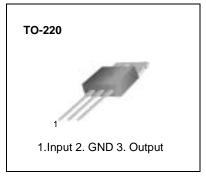
# 3-Terminal 3A Positive Voltage Regulator

#### **Features**

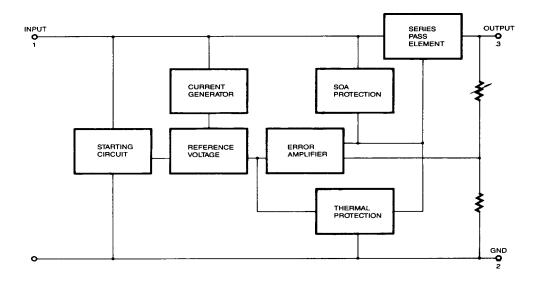
- Output current in excess of 3.0A
- Output transistor safe operating area compensation
- Power dissipation :25W
- · Internal short circuit current limiting
- · Internal thermal overload protection
- Output voltage offered in 4% tolerance
- No external components required
- Output voltage of 5,12 and 15V

### **Description**

This family of fixed voltage regulators are monolithic integrated circuit capable of driving loads in excess of 3.0 A.



# **Internal Block Diagram**



## **Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Input Voltage (for V <sub>O</sub> = 5V to 12V) (for V <sub>O</sub> = 15V)	Vı	35 40	V V
Power Dissipation	PD	Internally limited	
Thermal Resistance, Junction to Air Tc = +25 °C	RθJA	65	°C/W
Thermal Resistance ,Junction to Case	RθJC	2.5	°C/W
Operating Junction Temperature Range	TJ	0 ~ +150	°C
Storage Temperature Range	TSTG	-65 ~ +150	°C

# **Electrical Characteristics(MC78T05)**

(VI = 10V, IO = 3.0 A, 0 °C  $\leq$  TJ  $\leq$  +125 °C, Po  $\leq$  PMAX , unless otherwise specified. )

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Output Voltage	Vo	5mA ≤ lo ≤ 3.0A , T <sub>J</sub> = +25 °C 7.3V ≤ VI ≤ 20V, 5mA ≤ lo ≤ 2.0A	4.8 4.75	5.0 5.0	5.2 5.25	V
Line Regulation (Note1)	ΔVο	7.2V ≤ VI ≤ 35V , Io=5mA, TJ =+25 °C 7.2V ≤ VI ≤ 35V , Io=1.0A, TJ = +25 °C 7.5V ≤ VI ≤ 20V, Io =2.0A 8.0V ≤ VI ≤ 12V, Io =3.0A		3.0	2.5	mV
Load Regulation (Note1)	ΔVο	$5\text{mA} \le \text{lo} \le 3.0\text{A}$ , $T_J = +25$ °C $5\text{mA} \le \text{lo} \le 3.0\text{A}$	-	10 15	30 80	mV mV
Thermal Regulation	REGT	Pulse =10ms, P = 20W TA = +25 °C	-	0.002	0.03	%Vo/W
Quiescent Current	IQ	$5\text{mA} \le \text{lo} \le 3.0\text{A}$ , $T_J = +25$ °C $5\text{mA} \le \text{lo} \le 3.0\text{A}$	-	3.5 4.0	5.0 6.0	mA mA
Quiescent Current Change	ΔlQ	$7.2V \le VI \le 35V$ , $Io = 5mA$ $T_J = +25 ^{\circ}C$ ; $7.5V \le VI \le 20V$ , $Io = 2.0A$ ; $5mA \le Io \le 3.0A$	-	0.1	0.8	mA
Ripple Rejection	RR	$f = 120Hz, 8V \le V_I \le 18V, I_0 = 2.0A$	-	75	-	dB
Dropout Voltage	VD	lo = 3A ,TJ = +25 °C	-	2.2	2.5	V
Output Noise Voltage	VN	$T_A = +25 ^{\circ}C$ , $10Hz \le f \le 100KHz$	-	10	-	μV/Vo
Peak Output Current	IPK	TA = +25 °C	-	5.0	-	Α
Output Resistance	Ro	f = 1.0kHz	-	2.0	-	mΩ
Short Circuit Current Limit	Isc	VI = 35V, TJ =+25 °C	-	1.5	2.5	Α
Average Temperature Coefficient of Output Voltage	ΔVΟ/ΔΤ	Io = 5.0mA	-	0.2	-	mV/°C

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Change in Vo due heating effects must be taken into account separately. Pulse testing with low duty is used .( PMAX = 25W)

## **Electrical Characteristics(MC78T12)**

(VI = 19V, IO = 3.0 A, 0 °C  $\leq$  TJ  $\leq$  +125 °C, Po  $\leq$  PMAX , unless otherwise specified. )

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Output Voltage	Vo	$5\text{mA} \le \text{lo} \le 3.0\text{A}$ , $T_J = +25$ °C $14.5\text{V} \le \text{VI} \le 27\text{V}$ , $5\text{mA} \le \text{lo} \le 2.0\text{A}$	11.5 11.4	12 12	12.5 12.8	V
Line Regulation (Note1)	ΔVο	$\begin{array}{l} 14.5 V \leq VI \leq 35 V \; , \; lo=5 mA, \; T_{J} = +25 \; ^{\circ}C \\ 14.5 V \leq VI \leq 35 V \; , \; lo=1.0 A, \; T_{J} = +25 \; ^{\circ}C \\ 14.9 V \leq VI \leq 28 V, \; lo = 2.0 A \\ 16 V \leq VI \leq 22 V, \; lo = 3.0 A \end{array}$		6.0	45	mV
Load Regulation (Note1)	ΔVο	$5\text{mA} \le \text{lo} \le 3.0\text{A}$ , T <sub>J</sub> =+25 °C $5\text{mA} \le \text{lo} \le 3.0\text{A}$	-	10 15	30 80	mV mV
Thermal Regulation	REGT	Pulse =10ms, P = 20W TA = +25 °C	-	0.002	0.03	%Vo/W
Quiescent Current	IQ	$5\text{mA} \le \text{lo} \le 3.0\text{A}$ , TJ =+25 °C $5\text{mA} \le \text{lo} \le 3.0\text{A}$	-	3.5 4.0	5.0 6.0	mA mA
Quiescent Current Change	ΔlQ	$14.5V \le VI \le 35V$ , $Io = 5mA$ $T_J = +25 ^{\circ}C$ ; $14.9V \le VI \le 27V$ , $Io = 2.0A$ ; $5mA \le Io \le 3.0A$	-	0.1	0.8	mA
Ripple Rejection	RR	$f = 120Hz, 15V \le V_I \le 25V, Io = 2.0A$	57	67	-	dB
Dropout Voltage	VD	lo = 3A ,T <sub>J</sub> =+25 °C	-	2.2	2.5	V
Output Noise Voltage	VN	TA =+25 °C, 10Hz ≤ f ≤ 100KHz	-	10	-	μV/Vo
Peak Output Current	IPK	T <sub>A</sub> =+25 °C	-	5.0	-	Α
Output Resistance	Ro	f = 1.0kHz	-	2.0	-	mΩ
Short Circuit Current Limit	Isc	VI = 35V, T <sub>J</sub> =+25 °C	-	1.5	2.5	Α
Average Temperature Coefficient of Output Voltage	ΔV <sub>O</sub> /ΔΤ	Io = 5.0mA	-	0.5	-	mV/°C

<sup>•</sup> Load and line regulation are specified at constant junction temperature. Change in Vo due heating effects must be taken into account separately. Pulse testing with low duty is used .( PMAX = 25W)

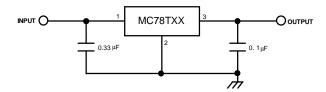
# **Electrical Characteristics(MC78T15)**

(VI = 23V, IO = 3.0 A, 0 °C  $\leq$  TJ  $\leq$  +125 °C, Po  $\leq$  PMAX , unless otherwise specified. )

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Output Voltage	Vo	$5\text{mA} \le \text{lo} \le 3.0\text{A}$ , $T_J = +25$ °C $17.5\text{V} \le \text{VI} \le 30\text{V}$ , $5\text{mA} \le \text{lo} \le 2.0\text{A}$	14.4 14.25	15 15	15.6 15.75	V
Line Regulation (Note1)	ΔVο	$17.6V \le VI \le 40V$ , $Io=5mA$ , $T_J = +25$ °C $17.6V \le VI \le 40V$ , $Io=1.0A$ , $T_J = +25$ °C $18V \le VI \le 30V$ , $Io = 2.0A$ $20V \le VI \le 26V$ , $Io = 3.0A$	-	7.5	55	mV
Load Regulation (Note1)	ΔVο	$5\text{mA} \leq \text{lo} \leq 3.0\text{A}$ , TJ =+25 °C $5\text{mA} \leq \text{lo} \leq 3.0\text{A}$	-	10 15	30 80	mV mV
Thermal Regulation	REGT	Pulse =10ms, P = 20W TA = +25 °C	-	0.002	0.03	%Vo/W
Quiescent Current	IQ	$5\text{mA} \le \text{lo} \le 3.0\text{A}$ , TJ =+25 °C $5\text{mA} \le \text{lo} \le 3.0\text{A}$	-	3.5 4.0	5.0 6.0	mA mA
Quiescent Current Change	ΔlQ	$17.6V \le VI \le 40V$ , $Io = 5mA$ $T_J = +25 ^{\circ}C$ ; $18V \le VI \le 30V$ , $Io = 2.0A$ ; $5mA \le Io \le 3.0A$	-	0.1	0.8	mA
Ripple Rejection	RR	$f = 120Hz, 18.5V \le V_I \le 28.5V, Io = 2.0A$	55	65	-	dB
Dropout Voltage	VD	lo = 3A ,T <sub>J</sub> =+25 °C	-	2.2	2.5	V
Output Noise Voltage	VN	T <sub>A</sub> =+25 °C, 10Hz ≤ f ≤ 100KHz	-	10	-	μV/Vo
Peak Output Current	lpk	T <sub>A</sub> =+25 °C - 5		5.0	-	Α
Output Resistance	Ro	f = 1.0kHz -		2.0	-	mΩ
Short Circuit Current Limit	Isc	VI = 40V, T <sub>J</sub> =+25 °C	-	1.0	2.0	Α
Average Temperature Coefficient of Output Voltage	ΔV <sub>O</sub> /ΔΤ	Io = 5.0mA	-	0.5	-	mV/°C

<sup>•</sup> Load and line regulation are specified at constant junction temperature. Change in Vo due heating effects must be taken into account separately. Pulse testing with low duty is used .( PMAX = 25W)

# **Typical Application**

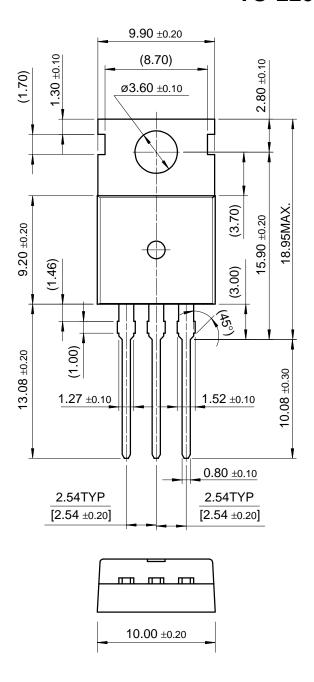


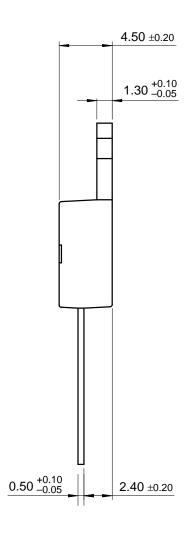
- 1. To specify an output voltage, substitute voltage value for "XX".
- 2. Bypass Capacitors are recommend for optimum stability and transient response and should be located as close as possible to the regulator

### **Mechanical Dimensions**

### Package

**TO-220** 





# **Ordering Information**

Product Number	Package	Operating Temperature
MC78T05CT		
MC78T12CT	TO-220	0 ~ + 125 °C
MC78T15CT		

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Datasheets for electronics components.



# MC78XX/LM78XX/MC78XXA

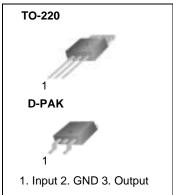
# 3-Terminal 1A Positive Voltage Regulator

#### **Features**

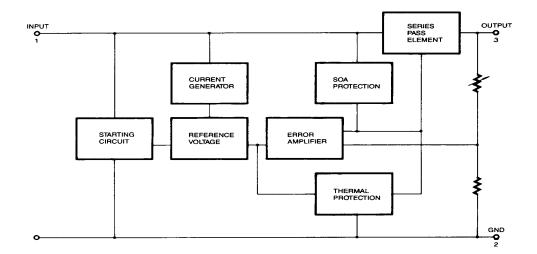
- Output Current up to 1A
- Output Voltages of 5, 6, 8, 9, 10, 12, 15, 18, 24V
- Thermal Overload Protection
- Short Circuit Protection
- Output Transistor Safe Operating Area Protection

### **Description**

The MC78XX/LM78XX/MC78XXA series of three terminal positive regulators are available in the TO-220/D-PAK package and with several fixed output voltages, making them useful in a wide range of applications. Each type employs internal current limiting, thermal shut down and safe operating area protection, making it essentially indestructible. If adequate heat sinking is provided, they can deliver over 1A output current. Although designed primarily as fixed voltage regulators, these devices can be used with external components to obtain adjustable voltages and currents.



### **Internal Block Digram**



## **Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Input Voltage (for V <sub>O</sub> = 5V to 18V) (for V <sub>O</sub> = 24V)	V <sub>I</sub> V <sub>I</sub>	35 40	V V
Thermal Resistance Junction-Cases (TO-220)	R <sub>0</sub> JC	5	°C/W
Thermal Resistance Junction-Air (TO-220)	RθJA	65	°C/W
Operating Temperature Range	TOPR	0 ~ +125	°C
Storage Temperature Range	TSTG	-65 ~ +150	°C

## **Electrical Characteristics (MC7805/LM7805)**

(Refer to test circuit ,0°C < TJ < 125°C, IQ = 500mA, VI = 10V, CI= 0.33 $\mu$ F, CQ= 0.1 $\mu$ F, unless otherwise specified)

Parameter	Symbol	Conditions		MC7	805/LM	7805	Unit
Parameter	Symbol		onations	Min.	Тур.	Max.	Unit
		TJ =+25 °C		4.8	5.0	5.2	
Output Voltage	Vo	$5.0$ mA $\leq$ Io $\leq$ VI = 7V to 20V	1.0A, Po ≤ 15W	4.75	5.0	5.25	V
Line Regulation (Note1)	Regline	T <sub>J=+25</sub> °C	Vo = 7V to 25V	-	4.0	100	mV
Line Regulation (Note I)	Regilile	11=+23 C	VI = 8V to 12V	-	1.6	50	IIIV
			IO = 5.0mA to1.5A	-	9	100	
Load Regulation (Note1)	Regload T <sub>J=+2</sub>	· · · · · · · · · · · · · · · · · · ·	I <sub>O</sub> =250mA to 750mA	-	4	50	mV
Quiescent Current	IQ	TJ =+25 °C		-	5.0	8.0	mA
Quiescent Current Change	Alo	IO = 5mA to 1.	0A	-	0.03	0.5	mΛ
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 7V to 25V		-	0.3	1.3	- mA
Output Voltage Drift	ΔV0/ΔΤ	Io= 5mA		-	-0.8	-	mV/°C
Output Noise Voltage	VN	f = 10Hz to 100	OKHz, TA=+25 °C	-	42	-	μV/Vo
Ripple Rejection	RR	f = 120Hz V <sub>O</sub> = 8V to 18V		62	73	-	dB
Dropout Voltage	V <sub>Drop</sub>	I <sub>O</sub> = 1A, T <sub>J</sub> =+25 °C		-	2	-	V
Output Resistance	rO	f = 1KHz		-	15	-	mΩ
Short Circuit Current	Isc	V <sub>I</sub> = 35V, T <sub>A</sub> =+25 °C		-	230	-	mA
Peak Current	IPK	TJ =+25 °C		-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Changes in  $V_0$  due to heating effects must be taken into account separately. Pulse testing with low duty is used.

# **Electrical Characteristics (MC7806)**

(Refer to test circuit  $,0^{\circ}C < T_{J} < 125^{\circ}C, \ I_{O} = 500 \text{mA}, \ V_{I} = 11 \text{V}, \ C_{I} = 0.33 \mu\text{F}, \ C_{O} = 0.1 \mu\text{F}, \ unless otherwise specified})$ 

Parameter	Cymbal	Conditions		l	MC7806	;	Unit
Parameter	Symbol		maitions	Min.	Тур.	Max.	Onit
		TJ =+25 °C		5.75	6.0	6.25	
Output Voltage	Vo	5.0mA ≤ I <sub>O</sub> ≤ V <sub>I</sub> = 8.0V to 21	1.0A, P <sub>O</sub> ≤ 15W √	5.7	6.0	6.3	V
Line Regulation (Note1)	Dogling	T <sub>J</sub> =+25 °C	V <sub>I</sub> = 8V to 25V	-	5	120	mV
Line Regulation (Note I)	Regline	1J =+25 C	V <sub>I</sub> = 9V to 13V	-	1.5	60	IIIV
Load Population (Note1)	Regload	TJ =+25 °C	IO =5mA to 1.5A	-	9	120	mV
Load Regulation (Note1)	Regioad 11 =+25	1J=+25 C	IO =250mA to750A	-	3	60	IIIV
Quiescent Current	IQ	T <sub>J</sub> =+25 °C		-	5.0	8.0	mA
Quiescent Current Change	Ma	I <sub>O</sub> = 5mA to 1A		-	-	0.5	mA
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 8V to 25V		-	-	1.3	IIIA
Output Voltage Drift	ΔV0/ΔΤ	IO = 5mA		-	-0.8	-	mV/°C
Output Noise Voltage	VN	f = 10Hz to 100K	Hz, TA =+25 °C	-	45	-	μV/Vo
Ripple Rejection	RR	f = 120Hz V <sub>I</sub> = 9V to 19V		59	75	-	dB
Dropout Voltage	V <sub>Drop</sub>	I <sub>O</sub> = 1A, T <sub>J</sub> =+25 °C		-	2	-	V
Output Resistance	ro	f = 1KHz		-	19	-	mΩ
Short Circuit Current	Isc	V <sub>I</sub> = 35V, T <sub>A</sub> =+2	25 °C	-	250	-	mA
Peak Current	IPK	TJ =+25 °C		-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Changes in V<sub>O</sub> due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7808)**

(Refer to test circuit ,0°C < T<sub>J</sub> < 125°C, I<sub>O</sub> = 500mA, V<sub>I</sub> =14V, C<sub>I</sub>= 0.33 $\mu$ F, C<sub>O</sub>= 0.1 $\mu$ F, unless otherwise specified)

Devemeter	Cumbal	C	onditions	N	MC7808		
Parameter	Symbol		Conditions		Тур.	Max.	Unit
		TJ =+25 °C		7.7	8.0	8.3	
Output Voltage	Vo	_	$5.0 \text{mA} \le I_{O} \le 1.0 \text{A}, P_{O} \le 15 \text{W}$ V <sub>I</sub> = 10.5V to 23V		8.0	8.4	V
Line Degulation (Nated)	Dogling	T	V <sub>I</sub> = 10.5V to 25V	-	5.0	160	\/
Line Regulation (Note1)	Regline $T_J = +25$ °C $V$	V <sub>I</sub> = 11.5V to 17V	-	2.0	80	mV	
Load Regulation (Note1)	Doglood	oad T <sub>J</sub> =+25 °C	I <sub>O</sub> = 5.0mA to 1.5A	-	10	160 mV	
Load Regulation (Note1)	Regload T <sub>J</sub> =+25	1J=+25 C	IO= 250mA to 750mA	-	5.0	80	IIIV
Quiescent Current	IQ	T <sub>J</sub> =+25 °C		-	5.0	8.0	mA
Quiagont Current Change	Alo	I <sub>O</sub> = 5mA to 1.0A		-	0.05	0.5	mA
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 10.5A to 25	/ <sub>I</sub> = 10.5A to 25V		0.5	1.0	
Output Voltage Drift	ΔV0/ΔΤ	IO = 5mA		-	-0.8	-	mV/°C
Output Noise Voltage	VN	f = 10Hz to 100KH	Hz, TA =+25 °C	-	52	_	μV/Vo
Ripple Rejection	RR	f = 120Hz, V <sub>I</sub> = 1	1.5V to 21.5V	56	73	-	dB
Dropout Voltage	VDrop	IO = 1A, TJ=+25 °C		-	2	-	V
Output Resistance	rO	f = 1KHz		-	17	-	mΩ
Short Circuit Current	Isc	V <sub>I</sub> = 35V, T <sub>A</sub> =+25 °C		-	230	-	mA
Peak Current	IPK	T <sub>J</sub> =+25 °C		-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Changes in Vo due to heating effects must be taken into account separately. Pulse testing with low duty is used.

# **Electrical Characteristics (MC7809)**

(Refer to test circuit ,0°C < T<sub>J</sub> < 125°C, I<sub>O</sub> = 500mA, V<sub>I</sub> =15V, C<sub>I</sub>= 0.33 $\mu$ F, C<sub>O</sub>= 0.1 $\mu$ F, unless otherwise specified)

Parameter	Cymbal	Conditions		MC7809			Unit
Parameter	Symbol		onditions	Min.	Тур.	Max.	Unit
		TJ =+25°C		8.65	9	9.35	
Output Voltage	Vo	5.0mA≤ I <sub>O</sub> ≤1.0A V <sub>I</sub> = 11.5V to 24V	•	8.6	9	9.4	V
Line Degulation (Note1)	Dogling	T25°C	V <sub>I</sub> = 11.5V to 25V	-	6	180	m\/
Line Regulation (Note1)	Regline	TJ=+25°C	VI = 12V to 17V	-	2	90	mV
Load Regulation (Note1)	Dogland	T25°C	I <sub>O</sub> = 5mA to 1.5A	-	12	180	m\/
Load Regulation (Note1)	Regload T <sub>J=+</sub>	TJ=+25°C	IO = 250mA to 750mA	-	4	90	- mV
Quiescent Current	IQ	T <sub>J</sub> =+25°C		-	5.0	8.0	mA
Quiescent Current Change	A.I.o.	IO = 5mA to 1.0A		-	-	0.5	mA
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 11.5V to 26	V	-	-	1.3	IIIA
Output Voltage Drift	ΔV0/ΔΤ	IO = 5mA		-	-1	-	mV/°C
Output Noise Voltage	VN	f = 10Hz to 100KH	lz, T <sub>A</sub> =+25 °C	-	58	-	μV/Vo
Ripple Rejection	RR	f = 120Hz V <sub>I</sub> = 13V to 23V		56	71	-	dB
Dropout Voltage	V <sub>Drop</sub>	I <sub>O</sub> = 1A, T <sub>J</sub> =+25°C		-	2	-	V
Output Resistance	ro	f = 1KHz		-	17	-	mΩ
Short Circuit Current	Isc	V <sub>I</sub> = 35V, T <sub>A</sub> =+2	5°C	-	250	-	mA
Peak Current	IPK	TJ= +25°C		-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Changes in V<sub>O</sub> due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7810)**

(Refer to test circuit ,0°C< TJ < 125°C, IO = 500mA, VI =16V, CI=  $0.33\mu F$ , CO= $0.1\mu F$ , unless otherwise specified)

Parameter	Cumbal	Conditions		Conditions MC7810			)	Unit
Parameter	Symbol		onations	Min.	Тур.	Max.	Oiiit	
		TJ =+25 °C		9.6	10	10.4		
Output Voltage	Vo	5.0mA ≤ I <sub>O</sub> ≤1.0A V <sub>I</sub> = 12.5V to 25		9.5	10	10.5	V	
Line Regulation (Note1)	Doglino	T25°C	V <sub>I</sub> = 12.5V to 25V	•	10	200	m\/	
	Regline	TJ =+25°C	VI = 13V to 25V	•	3	100	- mV	
Load Regulation (Note1)	Dogland	T25°C	I <sub>O</sub> = 5mA to 1.5A	-	12	200	m\/	
Load Regulation (Note1)	Regload T <sub>J</sub> =+25°C	IO = 250mA to 750mA	1	4	400	mV		
Quiescent Current	IQ	T <sub>J</sub> =+25°C		1	5.1	8.0	mA	
Quinagent Current Change	A.I.o.	I <sub>O</sub> = 5mA to 1.0A		1	-	0.5	mA	
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 12.5V to 29V		-	-	1.0		
Output Voltage Drift	ΔV0/ΔΤ	IO = 5mA		-	-1	-	mV/°C	
Output Noise Voltage	VN	f = 10Hz to 100KH	łz, TA =+25 °C	-	58	-	μV/Vo	
Ripple Rejection	RR	f = 120Hz V <sub>I</sub> = 13V to 23V			71	-	dB	
Dropout Voltage	V <sub>Drop</sub>	I <sub>O</sub> = 1A, T <sub>J</sub> =+25 °C		-	2	-	V	
Output Resistance	rO	f = 1KHz		-	17	-	mΩ	
Short Circuit Current	Isc	V <sub>I</sub> = 35V, T <sub>A</sub> =+2	V <sub>I</sub> = 35V, T <sub>A</sub> =+25 °C		250	-	mA	
Peak Current	IPK	TJ =+25 °C		-	2.2	-	Α	

#### Note

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Changes in V<sub>O</sub> due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7812)**

(Refer to test circuit ,0°C < TJ < 125°C, IO = 500mA, VI =19V, CI= 0.33 $\mu$ F, CO=0.1 $\mu$ F, unless otherwise specified)

Donomotor	Cymphol	Symbol Conditions		MC7812			Unit
Parameter	Symbol		Conditions		Тур.	Max.	Unit
		TJ =+25 °C		11.5	12	12.5	
Output Voltage	Vo	5.0mA ≤ I <sub>O</sub> ≤1.0A V <sub>I</sub> = 14.5V to 27\		11.4	12	12.6	V
Line Regulation (Note1)	Dogling	T 05.90	V <sub>I</sub> = 14.5V to 30V	-	10	240	mV
	Regline	TJ =+25 °C	VI = 16V to 22V	-	3.0	120	IIIV
Load Regulation (Note1)	Doglood	TJ =+25 °C	I <sub>O</sub> = 5mA to 1.5A	-	11	240	mV
Load Regulation (Note1)	Regload TJ =	IJ = +25 °C -	IO = 250mA to 750mA	-	5.0	120	IIIV
Quiescent Current	IQ	T <sub>J</sub> =+25 °C		-	5.1	8.0	mA
Quiescent Current Change	Alo	I <sub>O</sub> = 5mA to 1.0A		-	0.1	0.5	mA
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 14.5V to 30V		-	0.5	1.0	111/4
Output Voltage Drift	ΔV0/ΔΤ	IO = 5mA		-	-1	-	mV/ °C
Output Noise Voltage	VN	f = 10Hz to 100KH	z, TA =+25 °C	-	76	-	μV/Vo
Ripple Rejection	RR	f = 120Hz V <sub>I</sub> = 15V to 25V			71	-	dB
Dropout Voltage	V <sub>Drop</sub>	Io = 1A, TJ=+25	I <sub>O</sub> = 1A, T <sub>J</sub> =+25 °C		2	-	V
Output Resistance	rO	f = 1KHz		-	18	-	mΩ
Short Circuit Current	Isc	V <sub>I</sub> = 35V, T <sub>A</sub> =+2	5°C	-	230	-	mA
Peak Current	IPK	TJ = +25 °C		-	2.2	-	Α

#### Note

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Changes in V<sub>O</sub> due to heating effects must be taken into account separately. Pulse testing with low duty is used.

# **Electrical Characteristics (MC7815)**

(Refer to test circuit ,0°C < TJ < 125°C, IO = 500mA, VI =23V, CI=  $0.33\mu F$ , CO= $0.1\mu F$ , unless otherwise specified)

Parameter	Cumbal	Co	Conditions			MC7815			
Parameter	Symbol		onanions	Min.	Тур.	Max.	Unit		
		TJ =+25 °C		14.4	15	15.6			
Output Voltage	Vo	5.0mA ≤ I <sub>O</sub> ≤ 3 V <sub>I</sub> = 17.5V to 3	1.0A, P <sub>O</sub> ≤ 15W 30V	14.25	15	15.75	V		
Line Regulation (Nete1)	Doglino	TJ =+25 °C	V <sub>I</sub> = 17.5V to 30V	-	11	300	m\/		
Line Regulation (Note1)	Regline	1J=+25 C	VI = 20V to 26V	-	3	150	mV		
	ation (Note1) Regload T <sub>J</sub> =+25 °C		I <sub>O</sub> = 5mA to 1.5A	-	12	300			
Load Regulation (Note1)		TJ =+25 °C	IO = 250mA to 750mA	-	4	150	mV		
Quiescent Current	IQ	TJ =+25 °C		-	5.2	8.0	mA		
Quiagant Current Change	ΔlQ	I <sub>O</sub> = 5mA to 1.0A		-	-	0.5	mA		
Quiescent Current Change		VI = 17.5V to 30V		-	-	1.0			
Output Voltage Drift	ΔV <sub>O</sub> /ΔT	I <sub>O</sub> = 5mA		-	-1	-	mV/°C		
Output Noise Voltage	VN	f = 10Hz to 100	KHz, T <sub>A</sub> =+25 °C	-	90	-	μV/Vo		
Ripple Rejection	RR	f = 120Hz V <sub>I</sub> = 18.5V to 2	28.5V	54	70	-	dB		
Dropout Voltage	V <sub>Drop</sub>	I <sub>O</sub> = 1A, T <sub>J</sub> =+25 °C		-	2	-	V		
Output Resistance	rO	f = 1KHz		-	19	-	mΩ		
Short Circuit Current	Isc	V <sub>I</sub> = 35V, T <sub>A</sub> =+25 °C		-	250	-	mA		
Peak Current	IPK	T <sub>J</sub> =+25 °C		-	2.2	-	Α		

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Changes in V<sub>O</sub> due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7818)**

(Refer to test circuit ,0°C < TJ < 125°C, IO = 500mA, VI =27V, CI= 0.33 $\mu$ F, CO=0.1 $\mu$ F, unless otherwise specified)

Parameter	Symbol	Conditions		MC7818			Unit
Parameter	Symbol		onations	Min.	Тур.	Max.	Onit
		TJ =+25 °C		17.3	18	18.7	
Output Voltage	Vo	5.0mA ≤ I <sub>O</sub> ≤1.0A V <sub>I</sub> = 21V to 33V	A, P <sub>O</sub> ≤15W	17.1	18	18.9	V
Line Degulation (Note1)	Dogling	TJ =+25 °C	V <sub>I</sub> = 21V to 33V	-	15	360	mV
Line Regulation (Note1)	Regline	1J=+25 C	VI = 24V to 30V	-	5	180	IIIV
Load Regulation (Note1)	Regload	TJ =+25 °C	I <sub>O</sub> = 5mA to 1.5A	-	15	360	mV
Load Regulation (Note1)	Regioad 1J=+25 C	IO = 250mA to 750mA	-	5.0	180	IIIV	
Quiescent Current	IQ	TJ =+25 °C		-	5.2	8.0	mA
Quiagant Current Change	ΔIO	IO = 5mA to 1.0A	I <sub>O</sub> = 5mA to 1.0A		-	0.5	mΛ
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 21V to 33V		-	-	1	mA
Output Voltage Drift	ΔV0/ΔΤ	IO = 5mA		-	-1	-	mV/°C
Output Noise Voltage	VN	f = 10Hz to 100KH	z, TA =+25 °C	-	110	-	μV/Vo
Ripple Rejection	RR	f = 120Hz V <sub>I</sub> = 22V to 32V			69	-	dB
Dropout Voltage	V <sub>Drop</sub>	I <sub>O</sub> = 1A, T <sub>J</sub> =+25 °C		-	2	-	V
Output Resistance	rO	f = 1KHz		-	22	-	mΩ
Short Circuit Current	Isc	VI = 35V, T <sub>A</sub> =+25	5°C	-	250	-	mA
Peak Current	IPK	TJ =+25 °C		-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Changes in V<sub>O</sub> due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7824)**

(Refer to test circuit ,0°C < TJ < 125°C, IO = 500mA, VI =33V, CI= 0.33 $\mu$ F, CO=0.1 $\mu$ F, unless otherwise specified)

Parameter	Symbol	bol Conditions		MC7824			Unit
Parameter	Symbol		onations	Min.	Тур.	Max.	Unit
		TJ =+25 °C		23	24	25	
Output Voltage	Vo	5.0mA ≤ I <sub>O</sub> ≤ 1.0. VI = 27V to 38V	A, P <sub>O</sub> ≤ 15W	22.8	24	25.25	V
Line Regulation (Note1)	Poglino	TJ =+25 °C	V <sub>I</sub> = 27V to 38V	-	17	480	mV
	Regline		VI = 30V to 36V	-	6	240	IIIV
Load Population (Note1)	Poglood	TJ =+25 °C	I <sub>O</sub> = 5mA to 1.5A	-	15	480	mV
Load Regulation (Note1)	Regload T <sub>J</sub> =+25	1J=+25 C	IO = 250mA to 750mA	-	5.0	240	IIIV
Quiescent Current	IQ	TJ =+25 °C		-	5.2	8.0	mA
Quiescent Current Change	A.I.o.	I <sub>O</sub> = 5mA to 1.0A		-	0.1	0.5	mA
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 27V to 38V		-	0.5	1	IIIA
Output Voltage Drift	ΔV0/ΔΤ	IO = 5mA		-	-1.5	-	mV/°C
Output Noise Voltage	VN	f = 10Hz to 100KH	z, TA =+25 °C	-	60	-	μV/Vo
Ripple Rejection	RR	f = 120Hz V <sub>I</sub> = 28V to 38V		50	67	-	dB
Dropout Voltage	V <sub>Drop</sub>	I <sub>O</sub> = 1A, T <sub>J</sub> =+25 °C		-	2	-	V
Output Resistance	rO	f = 1KHz		-	28	-	mΩ
Short Circuit Current	Isc	V <sub>I</sub> = 35V, T <sub>A</sub> =+25 °C		-	230	-	mA
Peak Current	IPK	TJ =+25 °C		-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Changes in V<sub>O</sub> due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7805A)**

(Refer to the test circuits.  $0^{\circ}$ C < T<sub>J</sub> <  $125^{\circ}$ C,  $I_0$  =1A, V I = 10V, C I=0.33 $\mu$ F, C O=0.1 $\mu$ F, unless otherwise specified)

Parameter	Symbol	Co	onditions	Min.	Тур.	Max.	Unit
		T <sub>J</sub> =+25 °C		4.9	5	5.1	
Output Voltage	Vo		$I_{O} = 5mA \text{ to } 1A, P_{O} \le 15W$ $V_{I} = 7.5V \text{ to } 20V$		5	5.2	V
		V <sub>I</sub> = 7.5V to 2 I <sub>O</sub> = 500mA	V <sub>I</sub> = 7.5V to 25V I <sub>O</sub> = 500mA		5	50	
Line Regulation (Note1)	Regline	VI = 8V to 12	V	-	3	50	mV
		T <sub>J</sub> =+25 °C	V <sub>I</sub> = 7.3V to 20V	-	5	50	
		1J=+25°C	V <sub>I</sub> = 8V to 12V	-	1.5	25	
Load Regulation (Note1)		T <sub>J</sub> =+25 °C I <sub>O</sub> = 5mA to 1	.5A	-	9	100	.,
	Regload	I <sub>O</sub> = 5mA to 1A		-	9	100	mV
		IO = 250mA to	IO = 250mA to 750mA		4	50	
Quiescent Current	IQ	T <sub>J</sub> =+25 °C		-	5.0	6	mA
		IO = 5mA to 1A		-	-	0.5	
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 8 V to 25V, I <sub>O</sub> = 500mA		-	-	0.8	mA
Onlingo		V <sub>I</sub> = 7.5V to 20V, T <sub>J</sub> =+25 °C		-	-	0.8	
Output Voltage Drift	ΔV/ΔΤ	Io = 5mA		-	-0.8	-	mV/°C
Output Noise Voltage	VN	f = 10Hz to 10 T <sub>A</sub> =+25 °C	f = 10Hz to 100KHz T <sub>A</sub> =+25 °C			-	μV/Vo
Ripple Rejection	RR	f = 120Hz, IO V <sub>I</sub> = 8V to 18	-	68	-	dB	
Dropout Voltage	VDrop	IO = 1A, TJ =	-	2	-	V	
Output Resistance	ro	f = 1KHz		-	17	-	mΩ
Short Circuit Current	Isc	VI= 35V, TA =	=+25 °C	-	250	-	mA
Peak Current	IPK	T <sub>J</sub> = +25 °C		-	2.2	ı	А

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Change in Vo due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7806A)**

(Refer to the test circuits.  $0^{\circ}$ C < T<sub>J</sub> <  $125^{\circ}$ C,  $I_0$  =1A, V I =11V, C I=0.33 $\mu$ F, C O=0.1 $\mu$ F, unless otherwise specified)

Parameter	Symbol	Co	onditions	Min.	Тур.	Max.	Unit
		T <sub>J</sub> =+25 °C		5.58	6	6.12	
Output Voltage	Vo		$I_O = 5mA \text{ to } 1A, P_O \le 15W$ V <sub>I</sub> = 8.6V to 21V		6	6.24	V
		V <sub>I</sub> = 8.6V to 25 I <sub>O</sub> = 500mA	5V	-	5	60	
Line Regulation (Note1)	Regline	V <sub>I</sub> = 9V to 13V	1	-	3	60	mV
		T <sub>J</sub> =+25 °C	V <sub>I</sub> = 8.3V to 21V	-	5	60	
		1J=+25 °C	V <sub>I</sub> = 9V to 13V	-	1.5	30	
Load Regulation (Note1)		T <sub>J</sub> =+25 °C I <sub>O</sub> = 5mA to 1	.5A	-	9	100	
Load Rogalation (Note 1)	Regload	I <sub>O</sub> = 5mA to 1A		-	4	100	mV
		IO = 250mA to 750mA		-	5.0	50	
Quiescent Current	IQ	T <sub>J</sub> =+25 °C		-	4.3	6	mA
		IO = 5mA to 1A	A	-	-	0.5	
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 9V to 25V, I <sub>O</sub> = 500mA		-	-	8.0	mA
		VI= 8.5V to 2°	1V, TJ =+25 °C	-	-	8.0	
Output Voltage Drift	ΔV/ΔΤ	IO = 5mA		-	-0.8	•	mV/°C
Output Noise Voltage	VN	f = 10Hz to 10 T <sub>A</sub> =+25 °C	00KHz	-	10	-	μV/Vo
Ripple Rejection	RR	f = 120Hz, IO = 500mA VI = 9V to 19V		-	65	-	dB
Dropout Voltage	VDrop	IO = 1A, TJ =+25 °C		-	2	-	V
Output Resistance	rO	f = 1KHz		-	17	-	mΩ
Short Circuit Current	Isc	VI= 35V, TA =	-+25 °C	-	250	-	mA
Peak Current	IPK	T <sub>J=+25</sub> °C			2.2	ı	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Change in Vo due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7808A)**

(Refer to the test circuits.  $0^{\circ}$ C < T<sub>J</sub> <  $125^{\circ}$ C,  $I_{0}$  =1A, V I = 14V, C I=0.33 $\mu$ F, C I=0.1 $\mu$ F, unless otherwise specified)

Parameter	Symbol	Co	onditions	Min.	Тур.	Max.	Unit
		T <sub>J</sub> =+25 °C		7.84	8	8.16	
Output Voltage	Vo	I <sub>O</sub> = 5mA to 1A, P <sub>O</sub> ≤15W V <sub>I</sub> = 10.6V to 23V		7.7	8	8.3	V
		V <sub>I</sub> = 10.6V to 2 I <sub>O</sub> = 500mA	25V	-	6	80	
Line Regulation (Note1)	Regline	V <sub>I</sub> = 11V to 17	V	-	3	80	mV
		TJ =+25 °C	V <sub>I</sub> = 10.4V to 23V	-	6	80	
		1J=+25 C	V <sub>I</sub> = 11V to 17V	-	2	40	
Load Regulation (Note1)		T <sub>J</sub> =+25 °C I <sub>O</sub> = 5mA to 1	1.5A	-	12	100	
(.tete.t/	Regload	I <sub>O</sub> = 5mA to 1A		-	12	100	mV
		IO = 250mA to 750mA		-	5	50	
Quiescent Current	IQ	T <sub>J</sub> =+25 °C		-	5.0	6	mA
		IO = 5mA to 1A		-	-	0.5	
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 11V to 25V, I <sub>O</sub> = 500mA		-	-	0.8	mA
		V <sub>I</sub> = 10.6V to 23V, T <sub>J</sub> =+25 °C		-	-	0.8	İ
Output Voltage Drift	ΔV/ΔΤ	IO = 5mA		-	-0.8	-	mV/°C
Output Noise Voltage	VN	f = 10Hz to 10 T <sub>A</sub> =+25 °C	00KHz	-	10	-	μV/Vo
Ripple Rejection	RR	f = 120Hz, I <sub>O</sub> V <sub>I</sub> = 11.5V to		-	62	-	dB
Dropout Voltage	V <sub>Drop</sub>	I <sub>O</sub> = 1A, T <sub>J</sub> =+25 °C		-	2	-	V
Output Resistance	rO	f = 1KHz		-	18	-	mΩ
Short Circuit Current	Isc	V <sub>I</sub> = 35V, T <sub>A</sub> =	=+25 °C	-	250	-	mA
Peak Current	IPK	TJ=+25 °C		-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Change in Vo due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7809A)**

(Refer to the test circuits.  $0^{\circ}$ C < T<sub>J</sub> <  $125^{\circ}$ C,  $I_0$  =1A, V I = 15V, C I=0.33 $\mu$ F, C I=0.1 $\mu$ F, unless otherwise specified)

Parameter	Symbol	Co	onditions	Min.	Тур.	Max.	Unit
		T <sub>J</sub> =+25°C		8.82	9.0	9.18	
Output Voltage	Vo		I <sub>O</sub> = 5mA to 1A, P <sub>O</sub> ≤15W V <sub>I</sub> = 11.2V to 24V		9.0	9.35	V
		V <sub>I</sub> = 11.7V to 2 I <sub>O</sub> = 500mA	25V	-	6	90	
Line Regulation (Note1)	Regline	V <sub>I</sub> = 12.5V to	19V	-	4	45	mV
		T,j =+25°C	V <sub>I</sub> = 11.5V to 24V	-	6	90	
		1J =+25 C	V <sub>I</sub> = 12.5V to 19V	-	2	45	
Load Regulation (Note1)	T <sub>J</sub> =+25°C I <sub>O</sub> = 5mA to 1.0A		-	12	100	.,	
,	Regload	I <sub>O</sub> = 5mA to 1.0A		-	12	100	mV
		IO = 250mA to 750mA		-	5	50	
Quiescent Current	IQ	TJ =+25 °C		-	5.0	6.0	mA
		VI = 11.7V to	25V, TJ=+25 °C	-	-	0.8	
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 12V to 25V, I <sub>O</sub> = 500mA		-	-	0.8	mA
		IO = 5mA to 1.0A		-	-	0.5	
Output Voltage Drift	ΔV/ΔΤ	IO = 5mA		-	-1.0	-	mV/ °C
Output Noise Voltage	VN	f = 10Hz to 10 T <sub>A</sub> =+25 °C	00KHz	-	10	-	μV/Vο
Ripple Rejection	RR	f = 120Hz, IO V <sub>I</sub> = 12V to 22		-	62	-	dB
Dropout Voltage	VDrop	I <sub>O</sub> = 1A, T <sub>J</sub> =+25 °C		-	2.0	-	V
Output Resistance	ro	f = 1KHz		-	17	-	mΩ
Short Circuit Current	Isc	VI= 35V, TA =	=+25 °C	-	250	-	mA
Peak Current	IPK	T <sub>J=+25</sub> °C		-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant, junction temperature. Change in Vo due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7810A)**

(Refer to the test circuits.  $0^{\circ}$ C < T<sub>J</sub> <  $125^{\circ}$ C,  $I_0$  =1A, V I = 16V, C I=0.33 $\mu$ F, C I=0.1 $\mu$ F, unless otherwise specified)

Parameter	Symbol	Co	onditions	Min.	Тур.	Max.	Unit
		T <sub>J</sub> =+25°C		9.8	10	10.2	
Output Voltage	Vo	I <sub>O</sub> = 5mA to 1A, P <sub>O</sub> ≤ 15W V <sub>I</sub> =12.8V to 25V		9.6	10	10.4	V
		V <sub>I</sub> = 12.8V to I <sub>O</sub> = 500mA	26V	-	8	100	
Line Regulation (Note1)	Regline	V <sub>I</sub> = 13V to 20	)V	-	4	50	mV
		T <sub>J</sub> =+25 °C	V <sub>I</sub> = 12.5V to 25V	-	8	100	
		1J =+25 C	V <sub>I</sub> = 13V to 20V	-	3	50	
Load Regulation (Note1)		$T_J = +25 \degree C$ IO = 5mA to ?	T <sub>J</sub> =+25 °C I <sub>O</sub> = 5mA to 1.5A		12	100	.,
	Regload	I <sub>O</sub> = 5mA to 1.0A		-	12	100	mV
		IO = 250mA to 750mA		-	5	50	1
Quiescent Current	IQ	T <sub>J</sub> =+25 °C		-	5.0	6.0	mA
		V <sub>I</sub> = 13V to 26V, T <sub>J</sub> =+25 °C		-	-	0.5	
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 12.8V to 25V, I <sub>O</sub> = 500mA		-	-	0.8	mA
		IO = 5mA to 1.0A		-	-	0.5	
Output Voltage Drift	ΔV/ΔΤ	IO = 5mA		-	-1.0	-	mV/ °C
Output Noise Voltage	VN	f = 10Hz to 1 T <sub>A</sub> =+25 °C	00KHz	-	10	-	μV/Vo
Ripple Rejection	RR	f = 120Hz, IO = 500mA V <sub>I</sub> = 14V to 24V		-	62	-	dB
Dropout Voltage	VDrop	IO = 1A, TJ =+25°C		-	2.0	-	V
Output Resistance	rO	f = 1KHz		-	17	-	mΩ
Short Circuit Current	Isc	VI= 35V, TA :	=+25 °C	-	250	-	mA
Peak Current	lpk	TJ=+25 °C		-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Change in Vo due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7812A)**

(Refer to the test circuits.  $0^{\circ}$ C < T<sub>J</sub> <  $125^{\circ}$ C,  $I_0$  =1A, V I = 19V, C I=0.33 $\mu$ F, C I=0.1 $\mu$ F, unless otherwise specified)

Parameter	Symbol	Co	onditions	Min.	Тур.	Max.	Unit
		T <sub>J</sub> =+25 °C		11.75	12	12.25	
Output Voltage	Vo	IO = 5mA to 7 V <sub>I</sub> = 14.8V to	1A, Po ≤15W 27V	11.5	12	12.5	V
		V <sub>I</sub> = 14.8V to I <sub>O</sub> = 500mA	30V	-	10	120	
Line Regulation (Note1)	Regline	V <sub>I</sub> = 16V to 22	2V	-	4	120	mV
		T <sub>J</sub> =+25 °C	V <sub>I</sub> = 14.5V to 27V	-	10	120	
		1J =+25 C	V <sub>I</sub> = 16V to 22V	-	3	60	
Load Regulation (Note1)		T <sub>J</sub> =+25 °C I <sub>O</sub> = 5mA to 1.5A		-	12	100	.,
	Regload	I <sub>O</sub> = 5mA to 1.0A		-	12	100	mV
		IO = 250mA to 750mA		-	5	50	
Quiescent Current	IQ	T <sub>J</sub> =+25°C		-	5.1	6.0	mA
		V <sub>I</sub> = 15V to 3	0V, TJ=+25 °C	-		0.8	
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 14V to 27V, I <sub>O</sub> = 500mA		-		0.8	mA
		IO = 5mA to 7	1.0A	-		0.5	
Output Voltage Drift	ΔV/ΔΤ	IO = 5mA		-	-1.0	-	mV/°C
Output Noise Voltage	VN	f = 10Hz to 10 T <sub>A</sub> =+25°C	00KHz	-	10	-	μV/Vο
Ripple Rejection	RR	f = 120Hz, IO V <sub>I</sub> = 14V to 2		-	60	-	dB
Dropout Voltage	VDrop	IO = 1A, T <sub>J</sub> =+25°C		-	2.0	-	V
Output Resistance	ro	f = 1KHz		-	18	ı	mΩ
Short Circuit Current	Isc	VI= 35V, TA :	=+25 °C	-	250	-	mA
Peak Current	IPK	T <sub>J=+25</sub> °C		-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Change in Vo due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7815A)**

(Refer to the test circuits.  $0^{\circ}$ C < T<sub>J</sub> <  $125^{\circ}$ C,  $I_0$  =1A, V I =23V, C I=0.33 $\mu$ F, C O=0.1 $\mu$ F, unless otherwise specified)

Parameter	Symbol		nditions	Min.	Тур.	Max.	Unit
		T <sub>J</sub> =+25 °C		14.7	15	15.3	
Output Voltage	Vo	-	IO = 5mA to 1A, PO ≤15W VI = 17.7V to 30V		15	15.6	V
		V <sub>I</sub> = 17.9V to 1 I <sub>O</sub> = 500mA	30V	-	10	150	
Line Regulation (Note1)	Regline	V <sub>I</sub> = 20V to 26	V	-	5	150	mV
		T <sub>J</sub> =+25°C	V <sub>I</sub> = 17.5V to 30V	-	11	150	
		1J=+25 C	V <sub>I</sub> = 20V to 26V	-	3	75	-
Load Regulation (Note1)	T <sub>J</sub> =+25 $^{\circ}$ C I <sub>O</sub> = 5mA to 1.5A		1.5A	-	12	100	
Lodd Hogaldion (Hotol)	Regload I <sub>O</sub> = 5mA	Io = 5mA to 1	1.0A	-	12	100	mV
		IO = 250mA to 750mA		-	5	50	
Quiescent Current	IQ	T <sub>J</sub> =+25 °C		-	5.2	6.0	mA
		V <sub>I</sub> = 17.5V to	30V, TJ =+25 °C	-	-	0.8	
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 17.5V to	30V, IO = 500mA	-	-	0.8	mA
		IO = 5mA to 1	I.0A	-	-	0.5	-
Output Voltage Drift	ΔV/ΔΤ	IO = 5mA		-	-1.0	-	mV/°C
Output Noise Voltage	VN	f = 10Hz to 10 T <sub>A</sub> =+25 °C	00KHz	-	10	-	μV/Vo
Ripple Rejection	RR	f = 120Hz, IO V <sub>I</sub> = 18.5V to		-	58	-	dB
Dropout Voltage	VDrop	IO = 1A, TJ =+25 °C		-	2.0	-	V
Output Resistance	ro	f = 1KHz		-	19	-	mΩ
Short Circuit Current	Isc	VI= 35V, TA =	=+25 °C	-	250	-	mA
Peak Current	IPK	T <sub>J=+25</sub> °C		-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Change in Vo due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7818A)**

(Refer to the test circuits.  $0^{\circ}$ C < T<sub>J</sub> <  $125^{\circ}$ C,  $I_0$  =1A, V I = 27V, C I=0.33 $\mu$ F, C I=0.1 $\mu$ F, unless otherwise specified)

Parameter	Symbol	Co	onditions	Min.	Тур.	Max.	Unit
		TJ =+25 °C		17.64	18	18.36	
Output Voltage	Vo		I <sub>O</sub> = 5mA to 1A, P <sub>O</sub> ≤15W V <sub>I</sub> = 21V to 33V		18	18.7	V
		V <sub>I</sub> = 21V to 33 I <sub>O</sub> = 500mA	3V	-	15	180	
Line Regulation (Note1)	Regline	V <sub>I</sub> = 21V to 33	3V	-	5	180	mV
		T <sub>J</sub> =+25 °C	V <sub>I</sub> = 20.6V to 33V	-	15	180	
		1) =+25 C	VI= 24V to 30V	-	5	90	
Load Regulation (Note1)		T <sub>J</sub> =+25°C I <sub>O</sub> = 5mA to 1.5A		-	15	100	.,
3, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1,	Regload	I <sub>O</sub> = 5mA to 1.0A		-	15	100	mV
		IO = 250mA to 750mA		-	7	50	
Quiescent Current	IQ	T <sub>J</sub> =+25 °C		-	5.2	6.0	mA
		V <sub>I</sub> = 21V to 33V, T <sub>J</sub> =+25 °C		-	-	0.8	
Quiescent Current Change	$\Delta$ lQ	V <sub>I</sub> = 21V to 33V, I <sub>O</sub> = 500mA		-	-	0.8	mA
		IO = 5mA to 1.0A		-	-	0.5	
Output Voltage Drift	ΔV/ΔΤ	IO = 5mA		-	-1.0	-	mV/ °C
Output Noise Voltage	VN	f = 10Hz to 1 T <sub>A</sub> =+25°C	00KHz	-	10	-	μV/Vo
Ripple Rejection	RR	f = 120Hz, IO = 500mA VI = 22V to 32V		-	57	-	dB
Dropout Voltage	VDrop	IO = 1A, TJ =+25°C		-	2.0	-	V
Output Resistance	rO	f = 1KHz		-	19	-	mΩ
Short Circuit Current	Isc	VI= 35V, TA :	=+25°C	-	250	-	mA
Peak Current	IPK	T <sub>J=+25</sub> °C		-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Change in Vo due to heating effects must be taken into account separately. Pulse testing with low duty is used.

## **Electrical Characteristics (MC7824A)**

(Refer to the test circuits.  $0^{\circ}$ C < T<sub>J</sub> <  $125^{\circ}$ C,  $I_0$  =1A, V I = 33V, C I=0.33 $\mu$ F, C O=0.1 $\mu$ F, unless otherwise specified)

Parameter	Symbol	Co	onditions	Min.	Тур.	Max.	Unit
		T <sub>J</sub> =+25 °C		23.5	24	24.5	
Output Voltage	Vo		I <sub>O</sub> = 5mA to 1A, P <sub>O</sub> ≤15W V <sub>I</sub> = 27.3V to 38V		24	25	V
		V <sub>I</sub> = 27V to 38 I <sub>O</sub> = 500mA	3V	-	18	240	
Line Regulation (Note1)	Regline	V <sub>I</sub> = 21V to 33	BV	-	6	240	mV
		T <sub>J</sub> =+25 °C	V <sub>I</sub> = 26.7V to 38V	-	18	240	
		1J =+25 C	VI= 30V to 36V	-	6	120	
Load Regulation (Note1)		T <sub>J</sub> =+25 °C I <sub>O</sub> = 5mA to 1.5A		-	15	100	.,
(	Regload	I <sub>O</sub> = 5mA to 1.0A		-	15	100	mV
		IO = 250mA to 750mA		-	7	50	
Quiescent Current	IQ	T <sub>J</sub> =+25 °C		-	5.2	6.0	mA
		V <sub>I</sub> = 27.3V to	38V, TJ =+25 °C	-	-	0.8	
Quiescent Current Change	ΔlQ	V <sub>I</sub> = 27.3V to 38V, I <sub>O</sub> = 500mA		-	-	0.8	mA
		IO = 5mA to 1.0A		-	-	0.5	
Output Voltage Drift	ΔV/ΔΤ	IO = 5mA		-	-1.5	-	mV/°C
Output Noise Voltage	VN	f = 10Hz to 10 T <sub>A</sub> = 25 °C	00KHz	-	10	-	μV/Vo
Ripple Rejection	RR	f = 120Hz, IO V <sub>I</sub> = 28V to 3		-	54	-	dB
Dropout Voltage	VDrop	IO = 1A, TJ =+25 °C		-	2.0	-	V
Output Resistance	ro	f = 1KHz		-	20	-	mΩ
Short Circuit Current	Isc	VI= 35V, TA =	=+25 °C	-	250	-	mA
Peak Current	IPK	T <sub>J=+25</sub> °C	-	-	2.2	-	Α

<sup>1.</sup> Load and line regulation are specified at constant junction temperature. Change in VO due to heating effects must be taken into account separately. Pulse testing with low duty is used.

# **Typical Perfomance Characteristics**

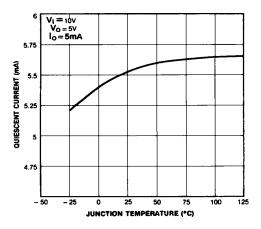


Figure 1. Quiescent Current

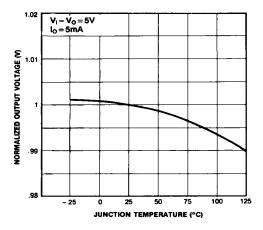


Figure 3. Output Voltage

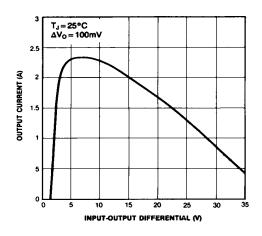


Figure 2. Peak Output Current

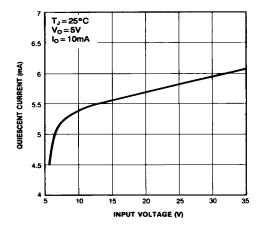


Figure 4. Quiescent Current

# **Typical Applications**

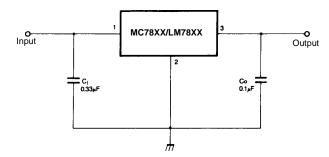


Figure 5. DC Parameters

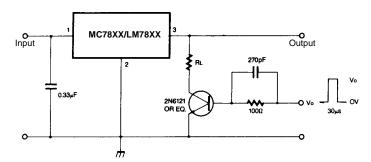


Figure 6. Load Regulation

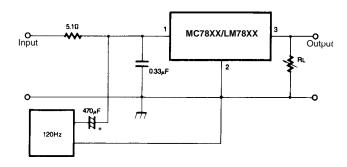


Figure 7. Ripple Rejection

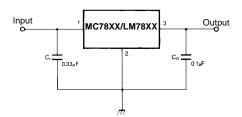


Figure 8. Fixed Output Regulator

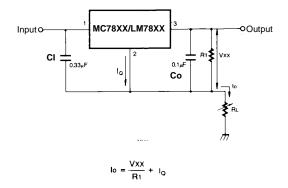
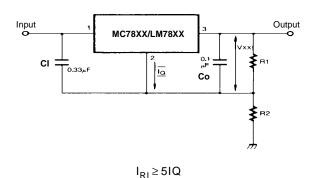


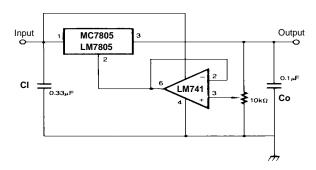
Figure 9. Constant Current Regulator

- (1) To specify an output voltage. substitute voltage value for "XX." A common ground is required between the input and the Output voltage. The input voltage must remain typically 2.0V above the output voltage even during the low point on the input ripple voltage.
- (2) C<sub>I</sub> is required if regulator is located an appreciable distance from power Supply filter.
- (3) Co improves stability and transient response.



 $V_O = V_{XX}(1+R_2/R_1)+I_QR_2$ 

Figure 10. Circuit for Increasing Output Voltage



 $I_{RI} \ge 5 I_{Q}$   $V_{Q} = V_{XX}(1+R_{2}/R_{1})+I_{Q}R_{2}$ 

Figure 11. Adjustable Output Regulator (7 to 30V)

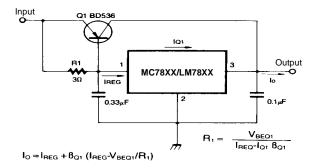


Figure 12. High Current Voltage Regulator

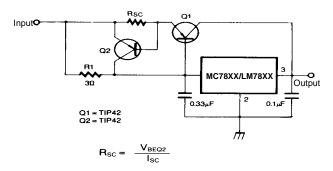


Figure 13. High Output Current with Short Circuit Protection

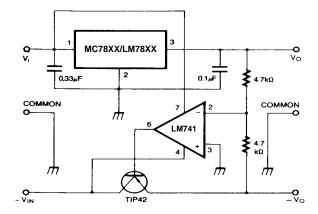


Figure 14. Tracking Voltage Regulator

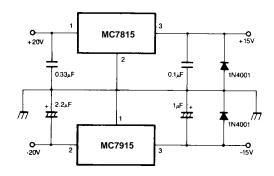


Figure 15. Split Power Supply (±15V-1A)

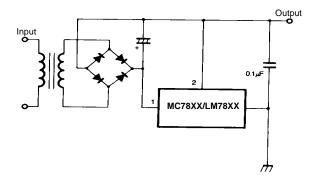


Figure 16. Negative Output Voltage Circuit

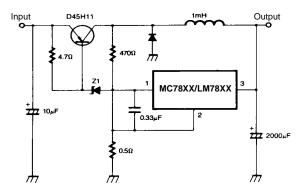
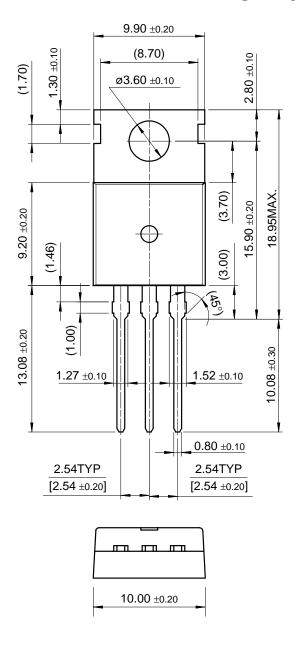


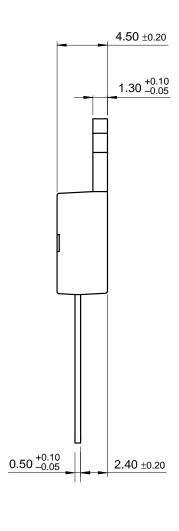
Figure 17. Switching Regulator

### **Mechanical Dimensions**

### Package

**TO-220** 

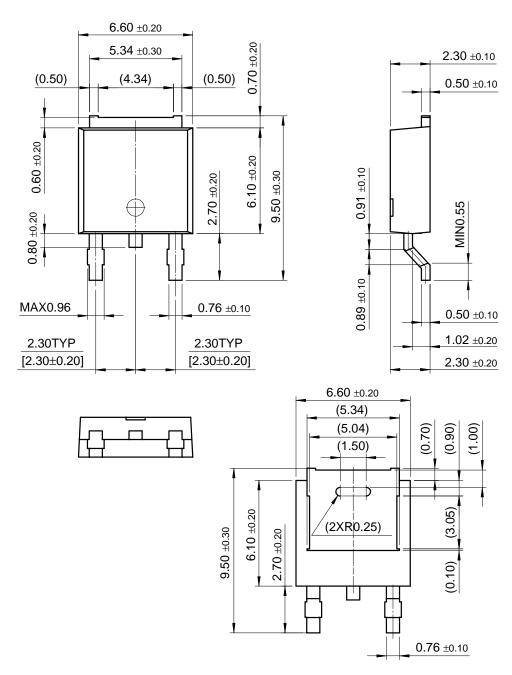




### **Mechancal Dimensions** (Continued)

### Package

# **D-PAK**



# **Ordering Information**

Product Number	Output Voltage Tolerance	Package	Operating Temperature
LM7805CT	±4%	TO-220	0 ~ + 125°C

Product Number	Output Voltage Tolerance	Package	Operating Temperature
MC7805CT			
MC7806CT			
MC7808CT			
MC7809CT			
MC7810CT		TO-220	
MC7812CT			
MC7815CT			
MC7818CT	±4%		
MC7824CT			
MC7805CDT			
MC7806CDT		D-PAK	
MC7808CDT			0 ~ + 125°C
MC7809CDT		D-I AIX	0~+1250
MC7810CDT			
MC7812CDT			
MC7805ACT			
MC7806ACT			
MC7808ACT			
MC7809ACT			
MC7810ACT	±2%	TO-220	
MC7812ACT			
MC7815ACT			
MC7818ACT			
MC7824ACT			

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- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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